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OBC/DCDC solution with Stellar-E MCU

NEV
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Center

Sep, NEV LAB, Shanghai
OBC system team



LV3 DFAE training agenda(26th Sep)

- Team member introduce —Arrow,ST,09:30-09:45
- Stellar-E MCU highlight feature for OBC/DCDC topology —Jacob,09:45-10:15
- ST product introduce for OBC/DCDC(SiC MOSFET,SBC) —Jacob,10:25-10:45
- 22kW combo solution introduce(requirement, solution structure, status) —Jacob,10:45-11:30
- 22kW combo system firmware develop introduce —Charos,13:30-14:30



OBC+DCDC LV3 DFAE training program

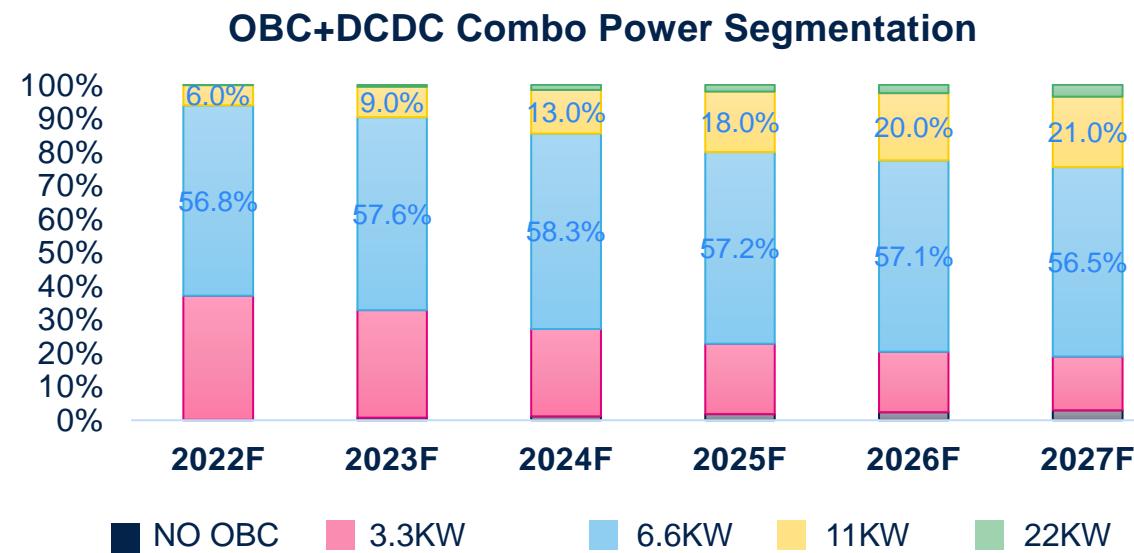
	ST LV3 DFAE technical support	Disty responsible & action required	Task duration time
Step1	<ul style="list-style-type: none">Stellar-E total solution training<ul style="list-style-type: none">Stellar-E highlight feature for OBC,DCDCSystem controller structure & topologyST highlight product introduce (SiC,SBC)22kW combo system solution introduce	<ul style="list-style-type: none">Vinfast current OBC,DCDC system block (topology, power, safety, controller structure)Market OBC,DCDC technical trend (power, safety, controller structure, OTA)Competitor solution information, key PN. and adv/disadv	WK2
Step2	<ul style="list-style-type: none">On site NEV CC co-work for customer prj<ul style="list-style-type: none">Set up NEV CC 22kw combo EVM for customer promotionCustomization development based NEV CC 22kw combo platform	<ul style="list-style-type: none">Assign AE/FAE to familiar 22kw combo EVM and able to setup EVM at CTM side for high power runningAssign AE/FAE to test/co-develop for customization requirement at system level	WK4
Step3	<ul style="list-style-type: none">Co-develop based Stellar-E 22kw combo platform<ul style="list-style-type: none">Single phase 6.6kW charging and inverting function R&D12V to 800V boost DCDC function R&D	<ul style="list-style-type: none">Assign R&D team and resource for solution developMonthly review status with ST team	WK24
Step4	<ul style="list-style-type: none">Customer prj support<ul style="list-style-type: none">MCAL · OS · BSW · RTE supportCDD L9396	<ul style="list-style-type: none">Assign FAE to support MCU configuration and integrationAssign FAE to support SBC register configure according customer requirement	WK24

OBC DCDC Market

- Leading by Local Player
- Dominate with OBC DCDC Combo solution

Project Leading Customer

Top 10 OBC Supplier	2021 (ku)	YoY	Y21 Market share
Vmax	603	211%	20.9%
FinDreams	455	217%	15.8%
Evtech (杭州富特)	343	178%	11.9%
Tesla(SANMINA-SCI)	312	125%	10.8%
TC charger (杭州铁城)	246	68%	8.5%
Shinry	207	146%	7.2%
Enpower	152	>500%	5.3%
Lihua	136	388%	4.7%
Kostal	119	150%	4.1%
Delta	64	-6%	2.2%
Total	2,636		



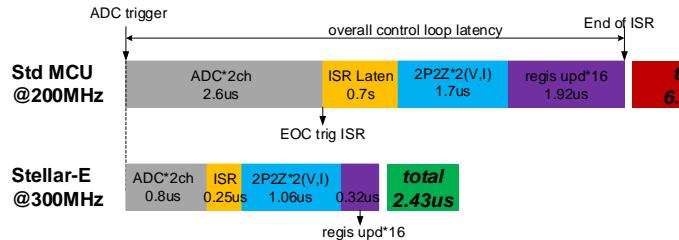
	2022F	2023F	2024F	2025F	2026F	2027F	CAGR Y22 vs Y27
China NEV (M sets)	5.8	7.5	10	12.6	15.1	17.2	24%
Growth Rate		29%	33%	26%	20%	14%	
SAM-Gate driver (M\$)	25.4	33.6	46.4	60.2	73.1	83.9	28%
SAM-SBC (M\$)	6.2	8.7	12.6	16.9	21.0	24.6	32%
SAM-MCU (M\$)	47.7	62.1	83.7	106.4	128.0	146.1	26%
SAM-Power Device (M\$)	170.9	233.6	335.9	451.8	559.1	656.3	31%



Stellar E MCU Series

Innovation with Value

Optimized for Power Conversion with SiC/GaN



FAST

- CPU power
- ADC&PWM access
- Protection

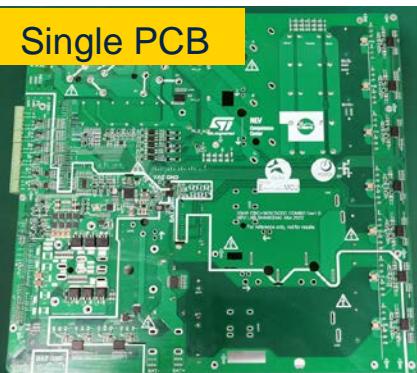
Safe and Secure ARM® Family

BEST

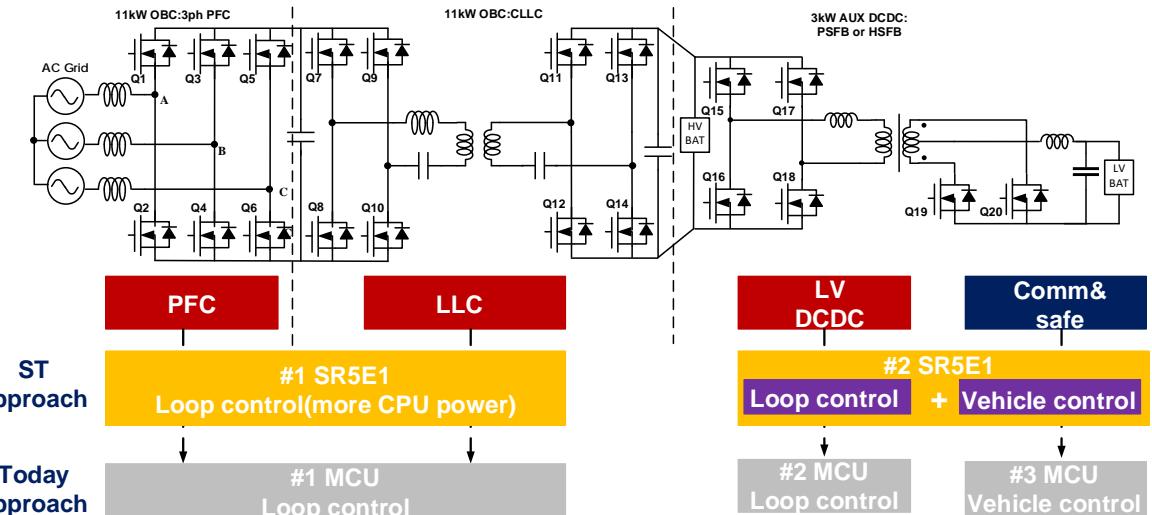
Real Time
Safety
Security



ECU System Cost Optimization



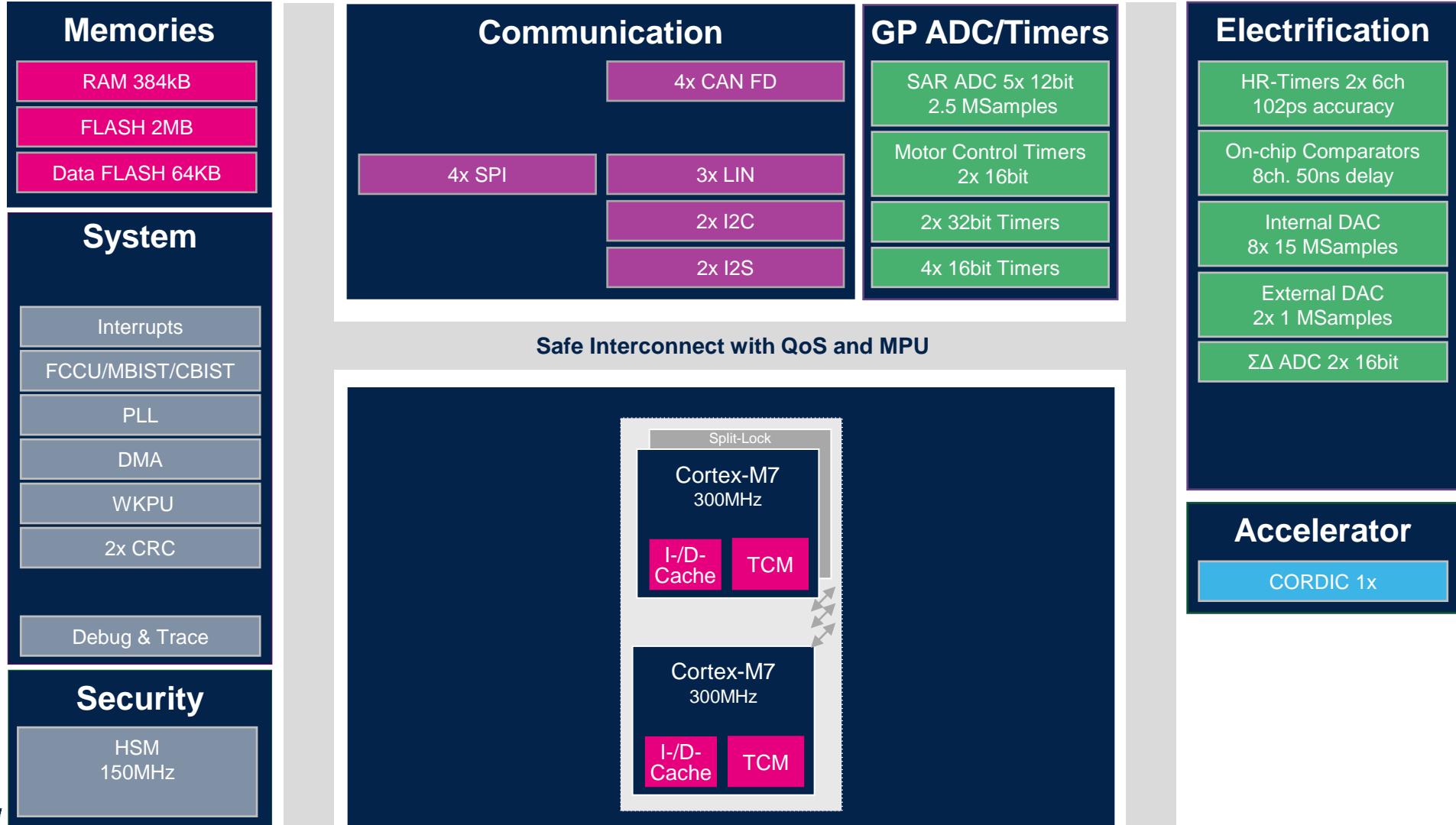
All System Control in
ONE MCU
to drive wide bandgap
Power Technologies





Stellar E1

Device Block Diagram





OBC+DCDC System Approach

Innovative Stellar Electrification MCU Family

Stellar-E technical highlight for OBC/DCDC

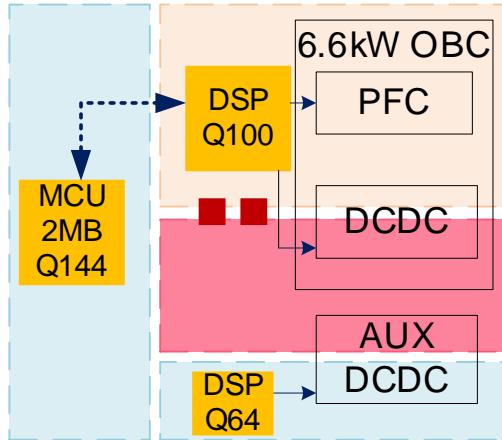


Benefits at system level

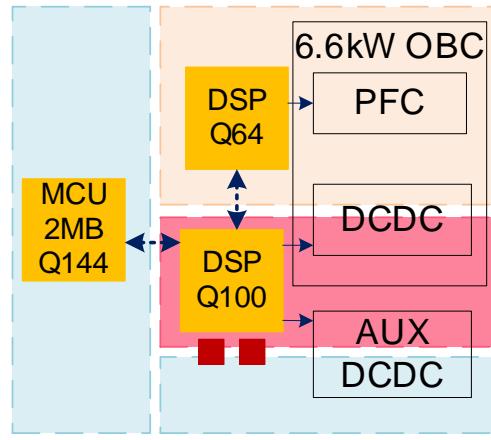
- Ultra-low latency control loop processing with optimized peripheral access and CPU power to best leverage SiC/GaN
 - High resolution PWM (104ps) to best leverage GaN/SiC, flexible PWM generation capability for complex topology(magnetic integration 3port DCDC)
 - Enhance analog with SARADC (2.5MSPS).analog comparator (fast protect & cycle by cycle PWM control) , and DAC(slope compensation for PCMC)
 - Function safety ASIL-D.ISO26262 compatible
 - CAN-FD and hardware OTA (A/B swap)
 - Hardware security module(HSM)
- increasing efficiency and extending driving mileage
 - saving transistor, mechanical size and higher power density
 - faster control response(dynamic load claimed by LV ECU)
 - safer power supply to LV ECU(LV3 autopilot)
 - low maintain cost
 - protect personal privacy

MCU solution BOM benchmark OBC+3KW AUX DCDC

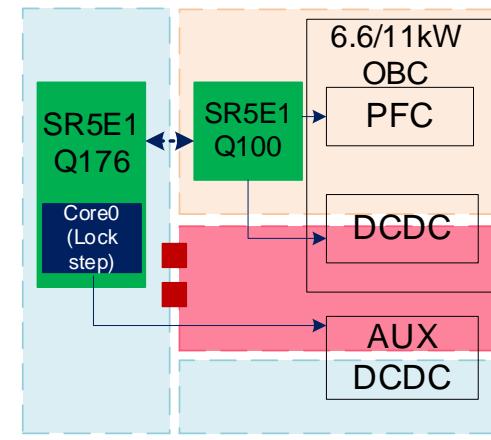
Solution1:2 DSP+1MCU



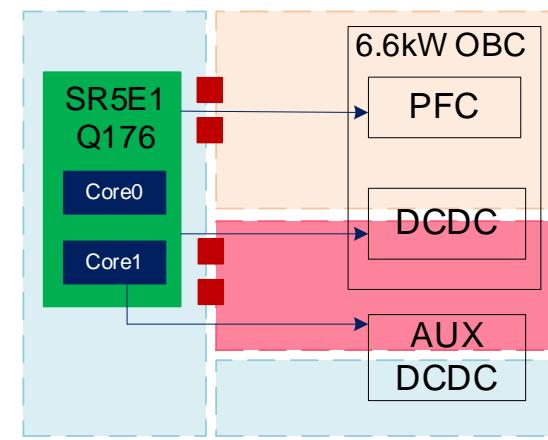
Solution2: 2 DSP+1MCU



Solution3: 1 DSP+1MCU



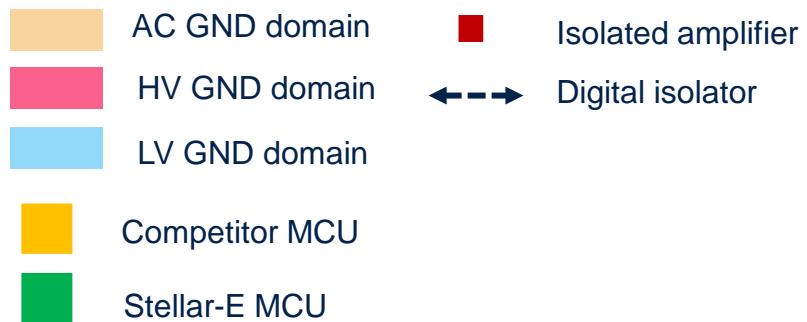
Solution4: 1MCU



Overall BOM benchmark(IC)

- LV SR5E1 replace DSP+MCU
- Peak current mode control(HW current loop)
- LV DCDC ASIL-C/D

- Single chip solution
- Peak current mode
- LV DCDC ASIL-B
- Isolation amplifier cost slight increase



Item	Solution1: 2DSP+1MCU	Solution2: 2DSP+1MCU	Solution3: 1 DSP+1 MCU	Solution4: 1MCU
MCU/DSP	DSP*2 MCU:2MB ASIL-D	DSP*2 MCU:2MB ASIL-D	DSP*1 MCU:SR5E1E7	MCU:SR5E1E7
Isolated amplifier	2ch	2ch	2ch	4ch
Digital isolator	4ch	8ch	4ch	0
Basic /reinforce /non-isolation gate driver	4+4+1	6+3	4+4+1	0+8+1



Stellar E MCU highlight for OBC/DCDC topology

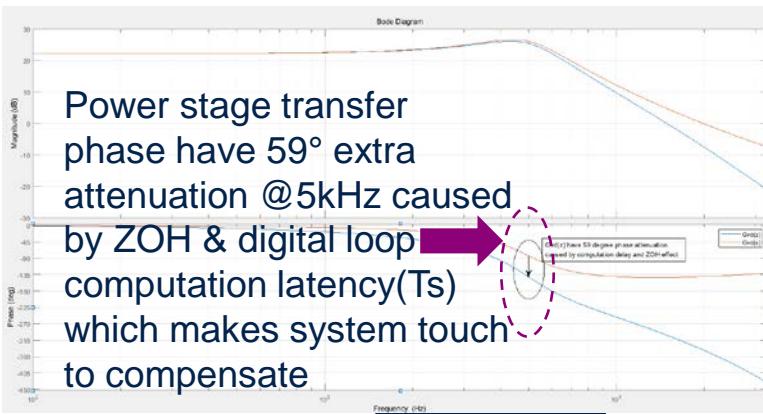
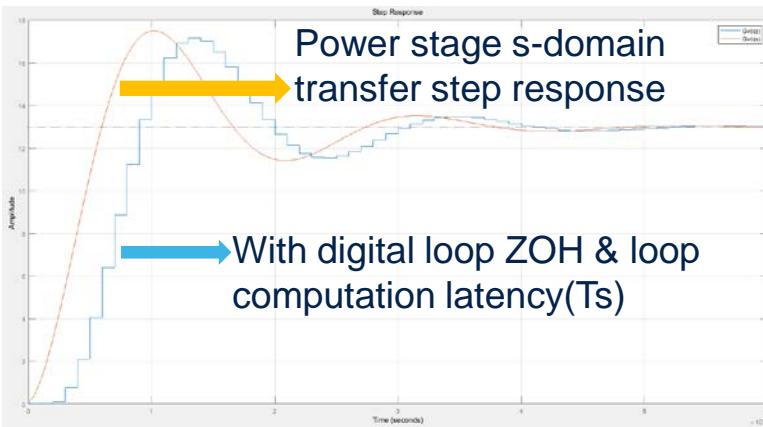
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May,2022

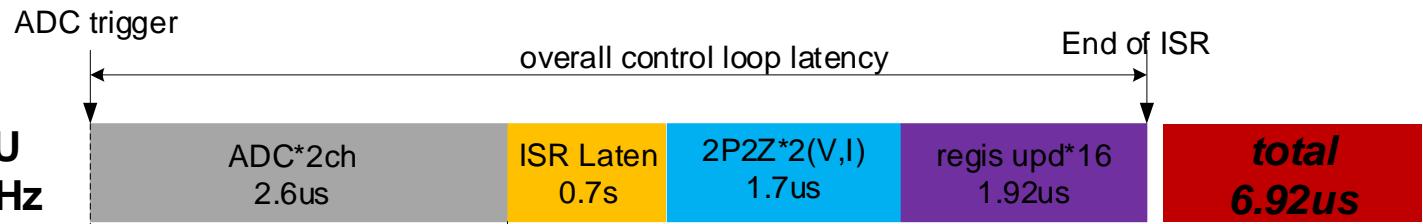


Faster control loop best leverage SiC/GaN

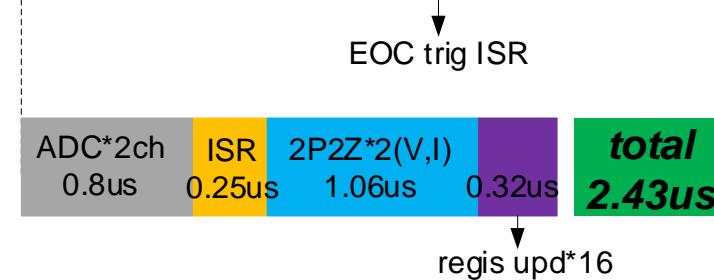
Digital control loop latency effect



**Std MCU
@200MHz**



**Stellar-E
@300MHz**



- Bode graph example with PSFB(400V→12V) power stage
- Loop computation delay=Ts(10us) defined from ADC SOC to PWM register updated.
- Control loop example with CLLC topology PFM+phase control.



X2~3

Switching Control Frequency to Leverage SiC/GaN

Scenario0:High resolution timer(HRTIM) for GaN/SiC

High resolution timer(HRTIM) address digital SMPS with high PWM switching frequencies

- Higher duty cycle resolution(Buck/boost...)
- Better accuracy on output voltage
- No limit cycling oscillation issues
- Higher frequency adjustment step resolution in resonant topology(LLC...)

	SiC/GaN freq	PWM counter	ADC granularity	PWM granularity	output control accuracy
Stellar-E PWM resolution -104ps	100kHz	96153	4.47mV/tick	0.24mV/tick	Good
	250kHz	38461	4.47mV/tick	0.6mV/tick	Good
	500kHz	19230	4.47mV/tick	1.2mV/tick	Good
	1MHz	9615	4.47mV/tick	2.4mV/tick	Good
STD MCU PWM resolution -10ns	100kHz	1000	4.47mV/tick	23.1mV/tick	No Good
	250kHz	400	4.47mV/tick	57.7mV/tick	No Good

Limit cycling oscillation issues:

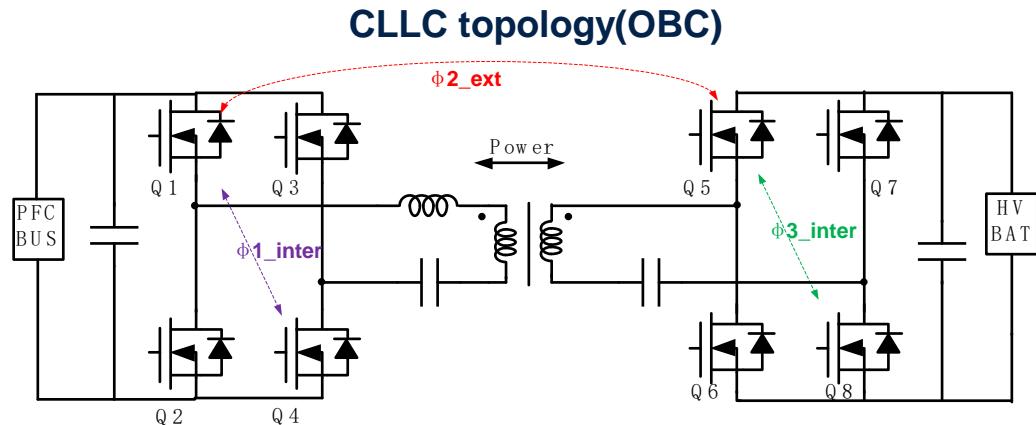
- Output voltage variation between two PWM ticks has to be equal or smaller than the smallest error variation(limited by voltage between two ADC ticks)

Example:

400-to-12V DC/DC with 18:1 turn ratio buck derived topology

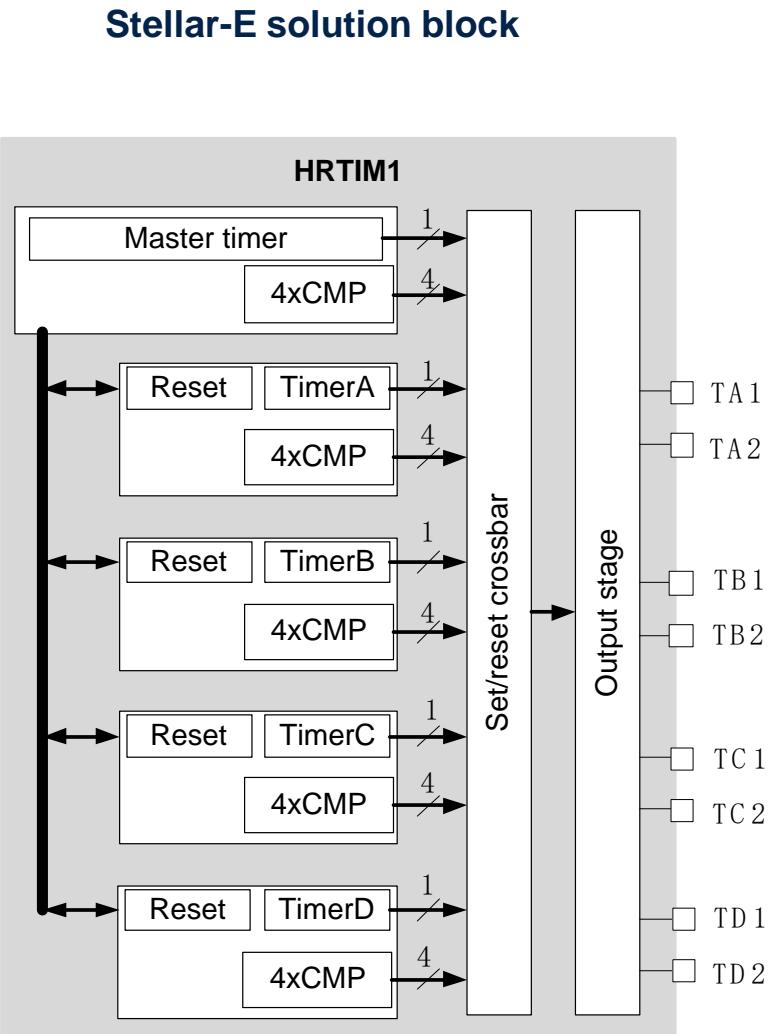
- Switching Frequency: 250 kHz
- Nominal Duty Cycle: 54%($V_o = V_{in} \cdot D \cdot n$)
- PWM Settings
 - Resolution: 1ns
 - Period: 4000 ticks
- ADC Settings:
 - ADC Reference Voltage: 3.3 V
 - ADC Resolution: 12-bit
 - Feedback Voltage Divider:
 - Divider Ratio (R_{up}/R_{dn}): 10k/ 2.2k
 - V_{fb_ADC} @ 12V: 2.164 V
- Input granularity(ADC): 4.46mV/tick
- Output granularity(PWM): 5.56mV/tick, larger than input granularity and has risk to happen limit cycling oscillation issue.

Scenario1:Serial resonant converter(CLLC) : PFM+phase shift control



Application requirement:

- Pulse frequency modulation(PFM) to all channel and synchronized
- Q1&Q4 internal phase shift φ_{1_inter} and phase shift direction fixed
- Q5&Q8 internal phase shift φ_{3_inter} and phase shift direction fixed
- Q1&Q5 external phase shift φ_{2_ext} and phase shift bi-direction configue
- eg:battery charging $\varphi_{2_ext} \in [0,90^\circ]$ · battery discharging $\varphi_{2_ext} \in [-90^\circ,0]$,angle=360°*(PWM rising edge delay time)/Ts. PWM lagging edge side as power topology output.
- Q1&Q2,Q3&Q4,Q5&Q6,Q7&Q8 complementary PWM with deadtime
- Typical switching frequency 100~200kHz
- All channel 50% duty cycle at steady state
- Phase shift & frequency not changing at same PWM cycle



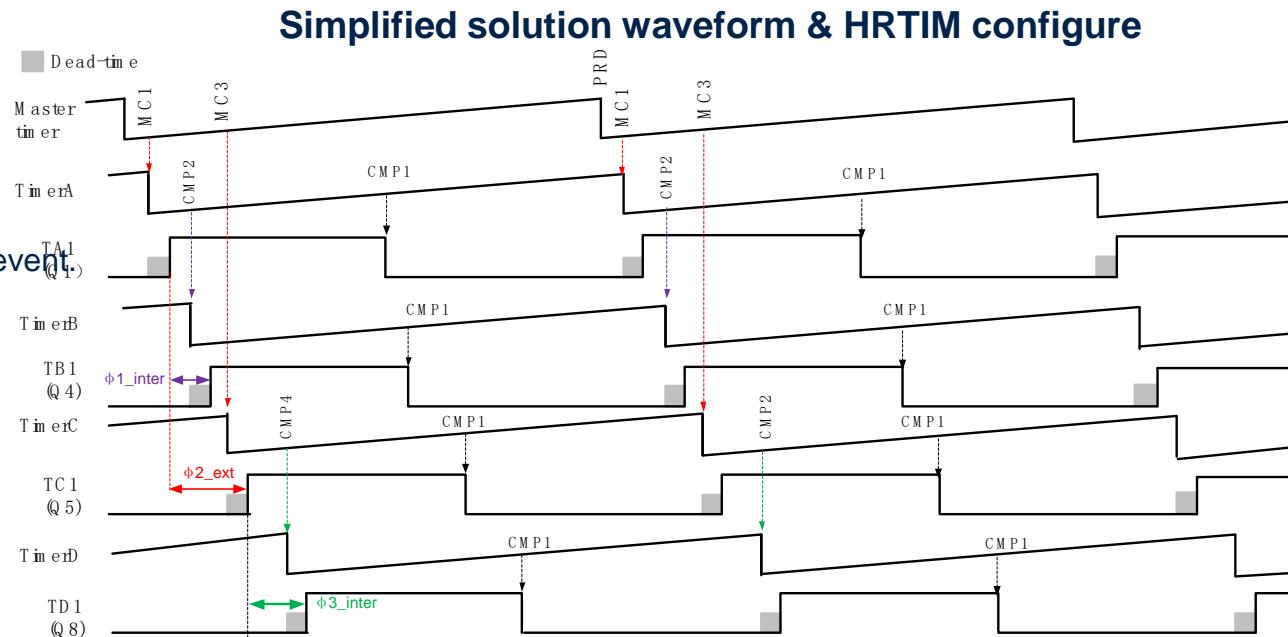
CLLC PFM + phase shift mix control: HRTIM multi-timer sync & flexible output manage

Solution benefits to system

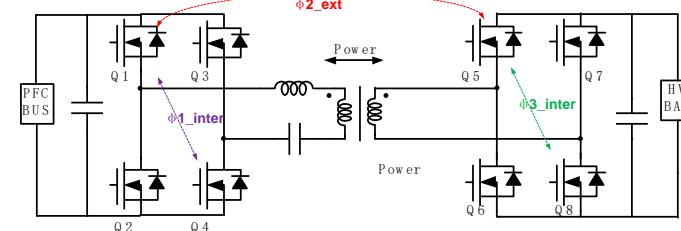
- Phase shift by control **one register** and off CPU load.
- Multi timer sync by hardware**, more robustness
- Flexible phase shift direction control by swap relative value of MC1,MC3
- All register update by global sync (Master.PER) or by timer itself counter reset event.

Solution analysis:

- Master timer MC1,MC3 reset Timer A,C to control external phase shift φ_2_{ext} and $\varphi_2_{ext}=\text{abs}(MC3-MC1)$.
- Relative value of MC1,MC3 controls phase shift direction.
 - MC3>MC1, $\varphi_2_{ext}>0$;
 - MC3<MC1, $\varphi_2_{ext}<0$;
- TimerA.CMP2 reset Timer B to control internal phase shift $\varphi_1_{inter}=TA.CMP2$
- TimerC.CMP4 reset Timer D to control internal phase shift $\varphi_3_{inter}=TC.CMP2$
- Timer A frequency controlled by proportional changed MC1 & master.PER.
- Output set/reset event may come from timer itself or other timers, refer to right table.

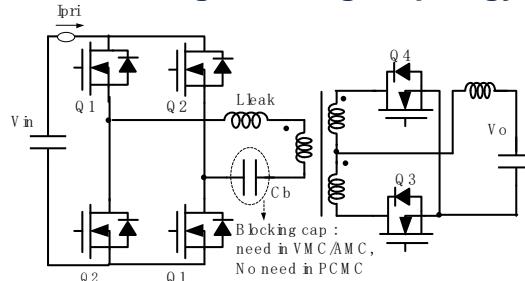


Source	Master timer	Timer						
		CMP1	CMP3	Period	TimerA	TimerB	TimerC	TimeD
Master counter reset								
TimerA counter reset								✓
TimerB counter reset								✓
TimerC counter reset								✓
TimerD counter reset								✓
TA1 output set					✓			
TA1 output reset								✓
TB1 output set						✓		
TB1 output reset							✓	
TC1 output set							✓	
TC1 output reset								✓
TD1 output set								✓
TD1 output reset								✓



Scenario2:hard switching full bridge(HSFB): Peak current mode control(PCM)

Hard switching full bridge topology



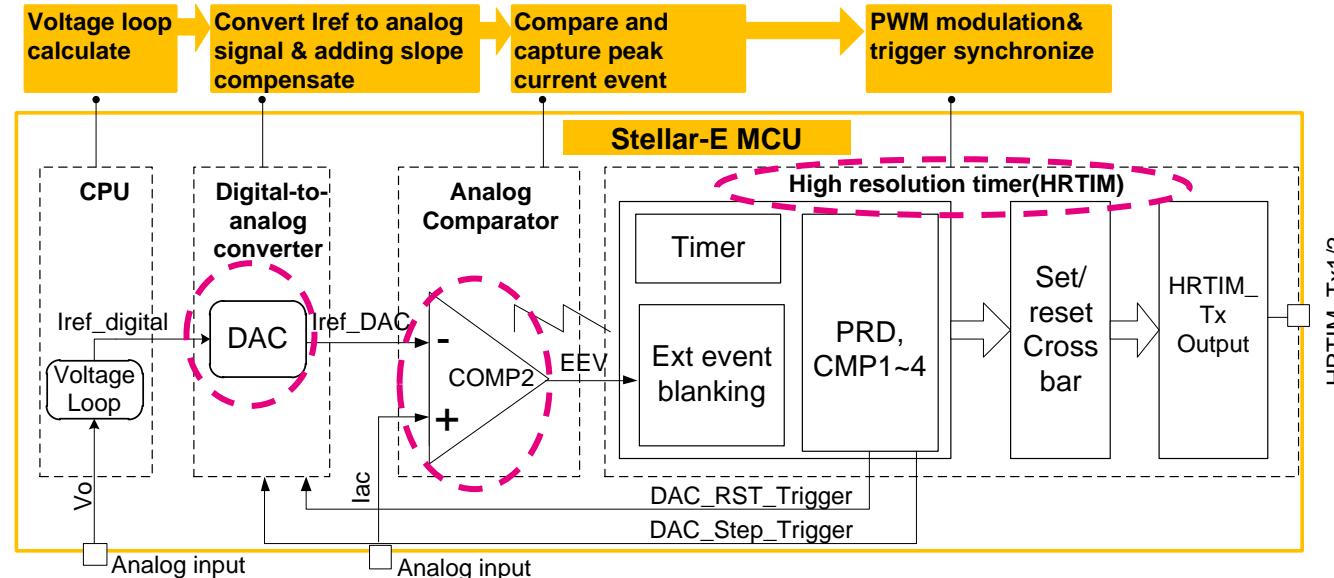
Application requirement:

- Peak current event modulate PWM width
- Q1-2 turn off controlled by comparator event at positive/negative half cycle respectively,Q1&Q4,Q2&Q3 complement with dead-time.
- Analog comparator need slope compensation
- Comparator event need blanking time at Q1,Q2 turn on to avoid false trigger

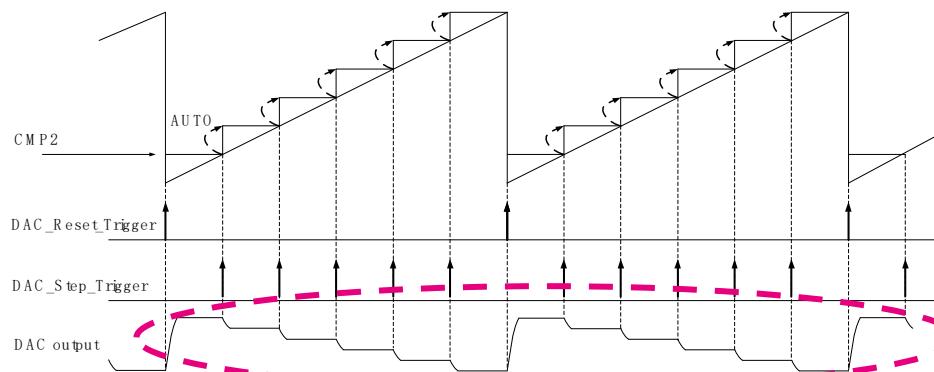
Solution analysis:

- Highlight peripheral : DAC converter, analog comparator, HRTIM PWM module
- Integrated analog comparator issue an event when primary peak current match comparator reference setting by DAC.
- DAC converts digital current reference to analog, dual DAC trigger configured to generate sawtooth reference as a slope compensation to diminish sub-harmonic oscillation in peak current mode control.
- Comparator event sent to HRTIM for PWM modulation. Event blanking used to prevent recovery noise at PWM start.

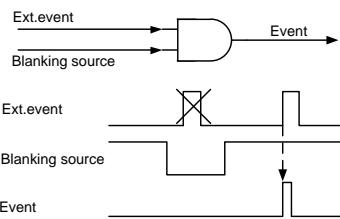
Stellar-E solution block



DAC sawtooth generator (slope compensate for COMP)



Event blanking mode



HSFB peak current mode control : Analog comparator +DAC+HRTIM

Solution analysis(continue):

- Master timer used to sync all slave timer.
- Timer C/E twice frequency of TimerA/B to distinguish positive & negative half cycle and two blanking window generate for positive & negative half cycle respectively.
- Comparator event within blanking window discarded and filter window define by zero to CMP1 match of Timer C/E. EEV_TX_CMP1 is comparator event filtered by CMP1 window and assign to reset TA1,TB1 output respectively.
- In case comparator event EEV_TX_CMP1 missing, TA.CMP1 match used to reset TA1 output to finish PWM cycle. Master.PRD for TB1 reset known as timeout protect.
- Dual trigger DAC generate sawtooth reference for comparator, called slope compensation to eliminate control loop sub-harmonic oscillation.
- Timer E generate two trigger for DAC. TimerE counter reset event reset DAC to sync sawtooth reference with PWM period. TE.CMP2 step trigger generates requests for incremental DAC value changes. Active comparison value for timerE is automatically updated as soon as a compare match occur.

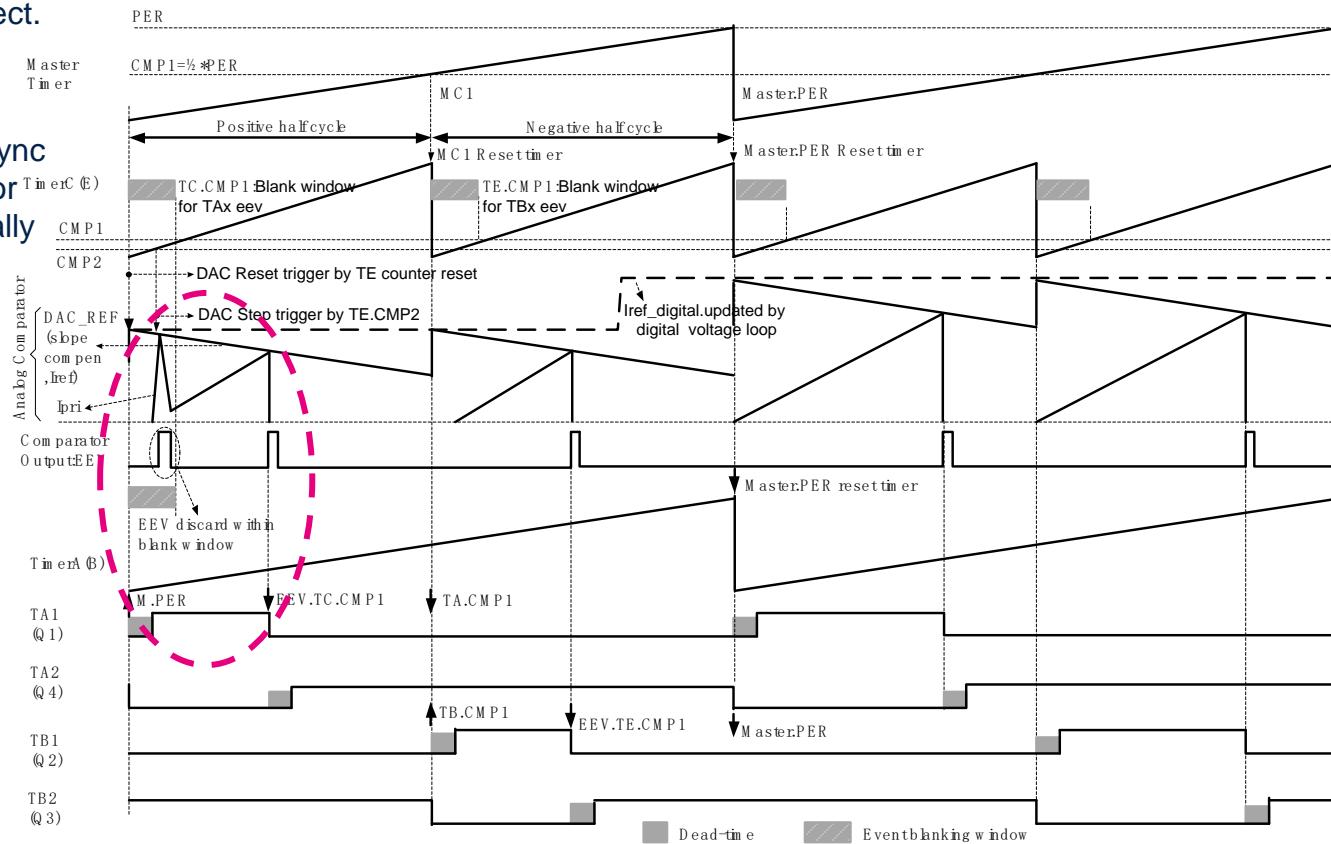
HRTIM configure

Source	Master timer	TimerA	TimerB	TimerC	TimerE							
	CMP1	Period	CMP1	CMP1	PRD	✓	CMP1_EEV	✓	CMP1_EEV	✓	CMP2	Reset
Comparator event blank window												
TimerA counter reset						✓						
TimerB counter reset						✓						
TimerC counter reset			✓	✓								
TimerE counter reset		✓	✓									
TA1 output set						✓						
TA1 output reset						✓						
TB1 output set							✓					
TB1 output reset							✓					
DAC reset trigger												✓
DAC step trigger												✓

Solution benefits to system

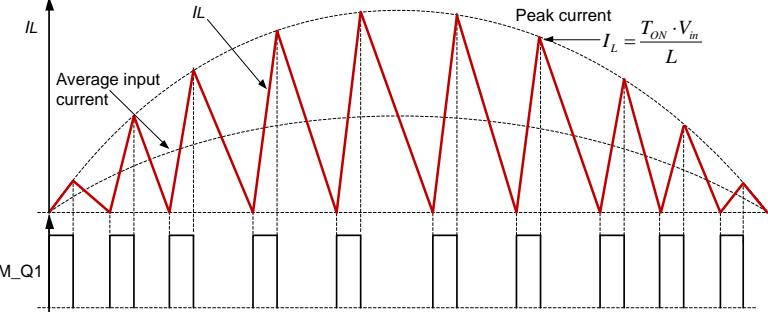
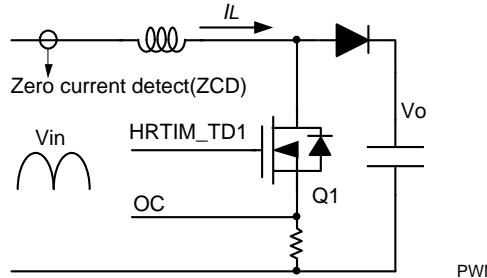
- No transformer blocking capacitor and cost/size saving
- Hardware current loop, no CPU load
- Cycle by cycle HW current limit
- Faster response, system degrade to one order

Simplified solution waveform



Scenario 3: Critical conduction mode PFC (CRM): 1MHz switching frequency with GaN

Boost topology & waveform



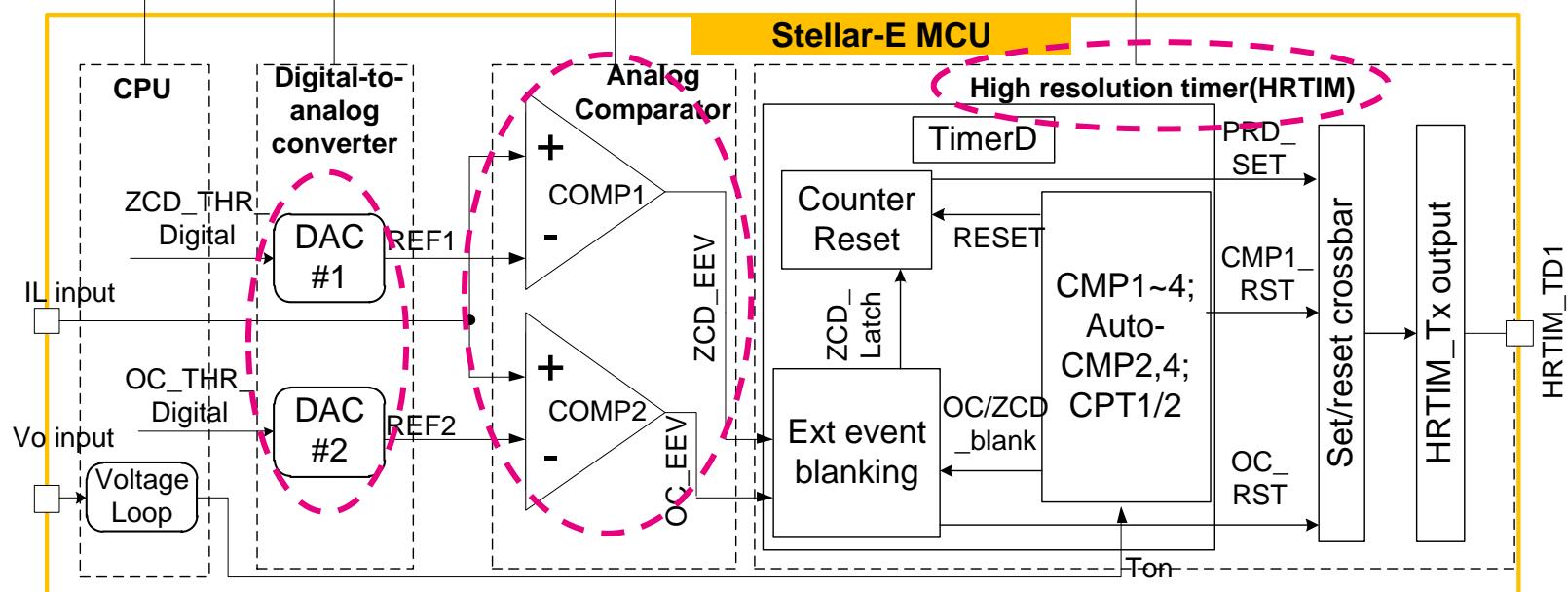
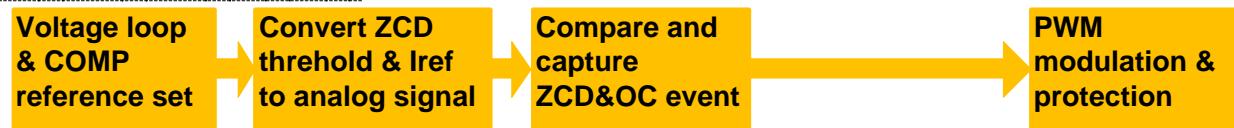
Application requirement

1. Constant TON time to build-up inductor current
2. TOFF time managed by inductor current decreased to zero event, controller restart next PWM cycle by inductor current zero crossing detection(ZCD).
3. Cycle by cycle current limit in case over current(OC) happens within TON and PWM recoverable at next cycle.
4. Max TOFF limit in case no zero current detect(ZCD) event to limit minimum PWM frequency
5. Min TOFF time limit in case too early ZCD event to limit maximum PWM frequency

Solution benefits to system

- Up to 1MHz with GaN, reducing inductor size and BOM cost.
- HRTIM(HW) control PWM TON & TOFF, NO CPU load
- Cycle by cycle current limit, flexible protect (OC or ZCD miss)

Stellar-E solution block



CRM PFC with GaN: HRTIM configure summary

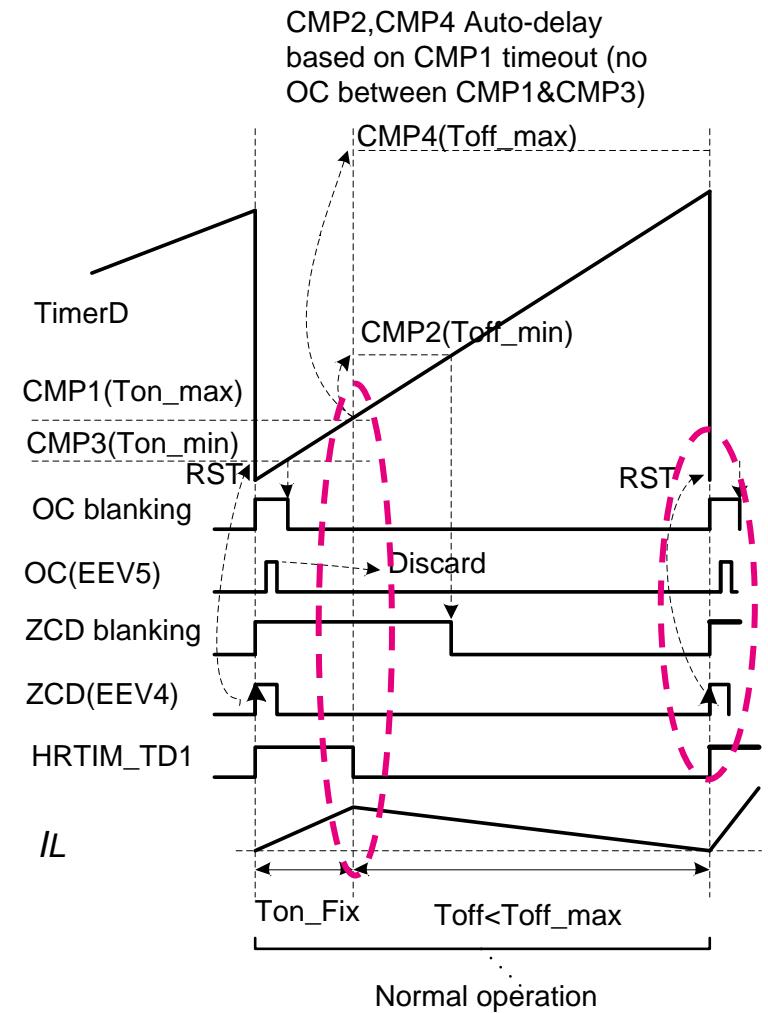
HRTIM configure

Source register/event		TimerD							
		CMP1	CMP2	CMP3	CMP4	Capture1	Capture2	Auto-delay_	Auto-delay_
Destination	Describe	Value	Software	=Counter value at TA1 reset	=Counter value at TA1 reset	=Capture1 + CMP2	=Capture2 + CMP4	OC_EEV_CMP3 ZCD_EEV_CMP2	
Active compare register		✓	x	✓	x				
Comparator1 ZCD EEV4 blank window							✓		
Comparator2 OC EEV5 blank window					✓				
TimerD counter reset							✓		✓
TD1 output set							✓		
TD1 output reset				✓				✓	

Solution analysis:

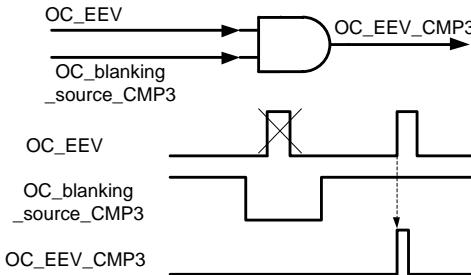
1. HRTIM_TD1(Q1) output :
 - SET by autodelay.CMP4 or ZCD_EEV_CMP2(ZCD event filtered by autodelay.CMP2)
 - RESET by TD.CMP1(fixed Ton time controlled) or OC_EVT_CMP3(current limit)
2. Timer D counter reset by
 - ZCD.EEV.CMP2
 - autodelay.CMP4 means timeout protect if no ZCD event happens
3. Capture1/2 define TOFF start moment, CMP2,CMP4 define minimum and maximum TOFF.

Simplified solution waveform



CRM PFC with GaN: Over current and maximum TOFF protect

Event blanking mode



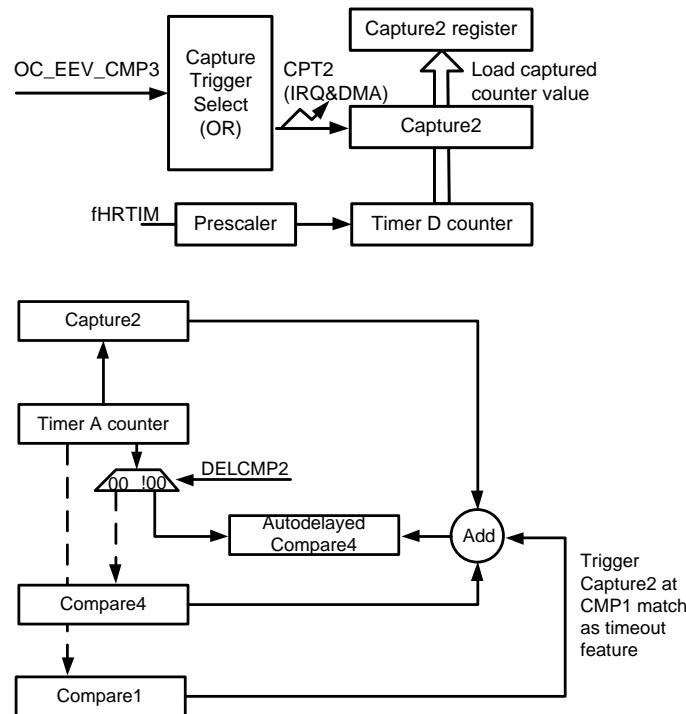
Application requirement

1. Cycle by cycle current limit in case over current(OC) happens within TON and PWM recoverable at next PWM cycle
2. Max TOFF limit in case no zero current detect(ZCD) event to limit minimum PWM frequency

Solution for item1 analysis:

1. Over current (OC) captured by analog comparator as an event used to reset TD1. A blanking window set by TD.CMP3 used to discard OC event if it's false triggered by diode recovery at PWM cycle start , OC blanking window also is TON_min.

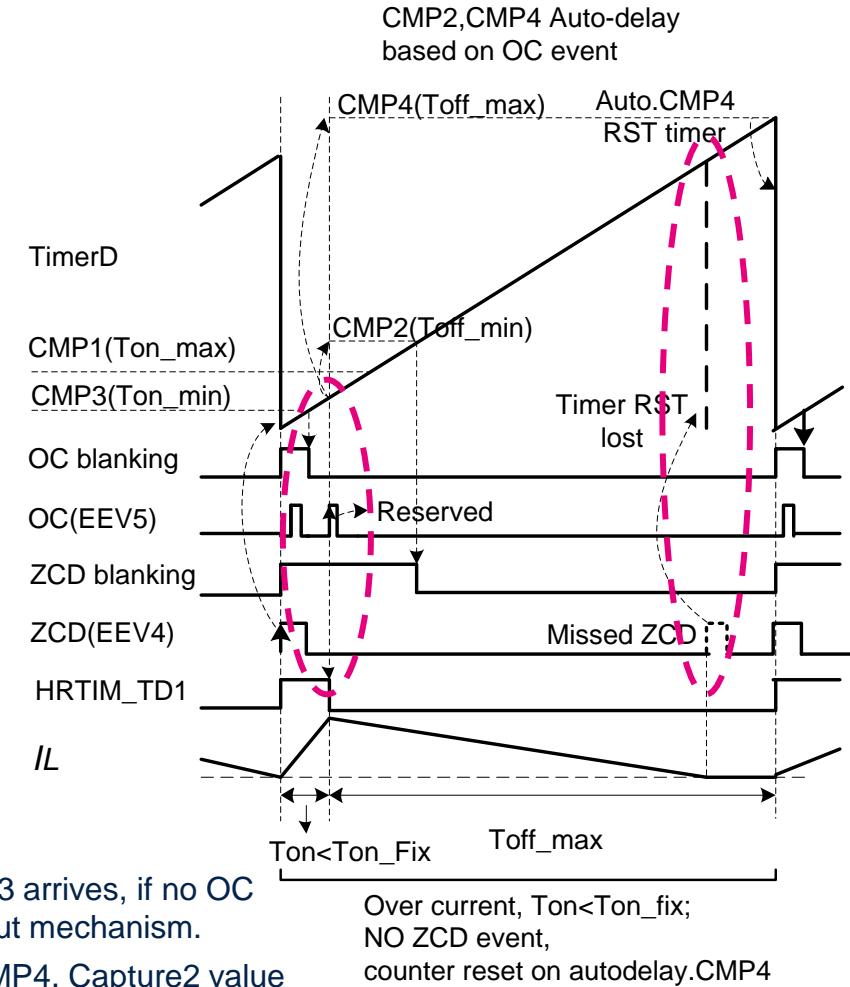
Timing unit capture & auto-delay compare



Solution for item2 analysis:

1. Capture2 register load counter value when OC_EEV_CMP3 arrives, if no OC event happens,CMP1 used to trigger capture unit as timeout mechanism.
2. Autodelay.CMP4 updated with value of capture2 adding CMP4. Capture2 value define TOFF start, CMP4 define maximum TOFF interval.
3. Autodelay.CMP4 reset counter in case ZCD event missing(timeout) to clamp minimum PWM frequency.

Simplified solution waveform

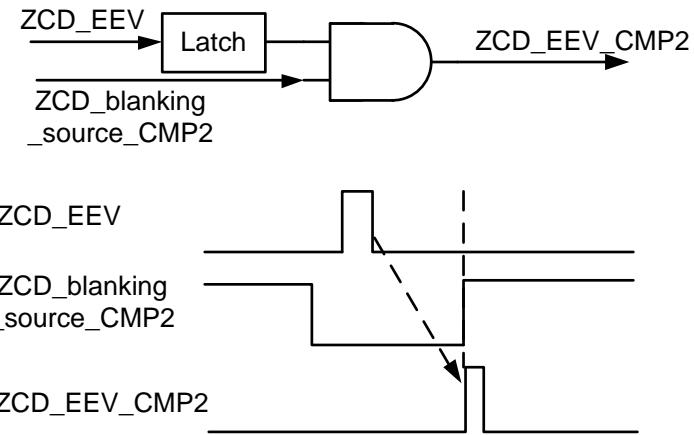


CRM PFC with GaN: Minimum TOFF protect

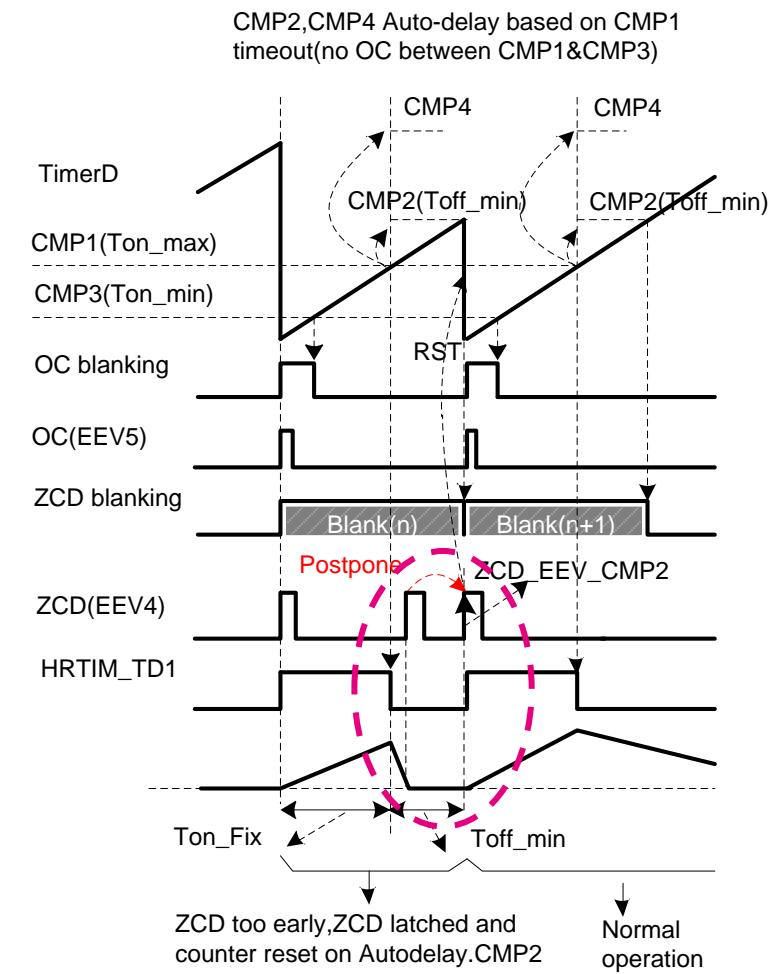
Application requirement

- Min TOFF time limit in case too early ZCD event to limit maximum PWM frequency

Event postpone mode



Simplified solution waveform



Solution analysis

- In case ZCD event arrive too early, a ZCD blanking window defined from timer counter reset to Autodelay.CMP2.
- If ZCD event happens during ZCD blanking window, it will not be discarded and will be latched to end of window as ZCD_EEV_CMP2 and will reset timer counter.
- Autodelay.CMP2 register updated with value of capture1 adding compare2. Capture1 define TOFF start, and CMP2 define minimum TOFF interval. Capture1 triggered by OC_EEV_CMP3 with CMP1 timeout mechanism.



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ST highlight product for OBC,DCDC

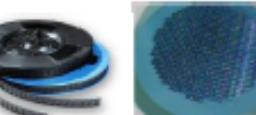
May,2022



STPOWER SiC MOSFET Positioning vs. product family & focus application



SiC MOSFET Package Roadmap

	PowerFLAT 8x8 STD & DSC	H2PAK-7L	HU3PAK	ACEPAK SMIT	HiP-247 (3 & 4 leads)	STPAK	Bare Dice
Package							
	Surface Mounting			Through-Hole		Special Package Solutions	
Characteristics	<ul style="list-style-type: none"> ▫ Very Thin (< 1mm) ▫ Well accepted in power conversion ▫ Dual side cooling option ▫ Leadless ▫ Industrial domain 	<ul style="list-style-type: none"> ▫ AG qualified at 175dC ▫ Kelvin Source for optimized driving ▫ High runner for Automotive customers 	<ul style="list-style-type: none"> ▫ AG qualified at 175dC ▫ Top side cooling ▫ Kelvin Source for optimized driving ▫ Very good thermal dissipation 	<ul style="list-style-type: none"> ▫ AG qualified at 175dC ▫ Isolated Top side cooling ▫ Suitable for different configurations (HB, Dual die, etc.) ▫ High Power ▫ Modular Approach 	<ul style="list-style-type: none"> ▫ AG qualified at 200dC ▫ Very common Industry standard ▫ Kelvin Source option for optimized driving ▫ High creepage version (1700V) in development 	<ul style="list-style-type: none"> ▫ Unique Solution for traction Inverter ▫ AG qualified at 200dC ▫ Very High thermal dissipation efficiency ▫ Sense pin for optimized driving ▫ Multi-sintered package 	<ul style="list-style-type: none"> ▫ WLBI & KGD ▫ T&R or RWF options ▫ Compliant with the most stringent Automotive Quality Requirements

Gen3 SiC MOSFET product Plan

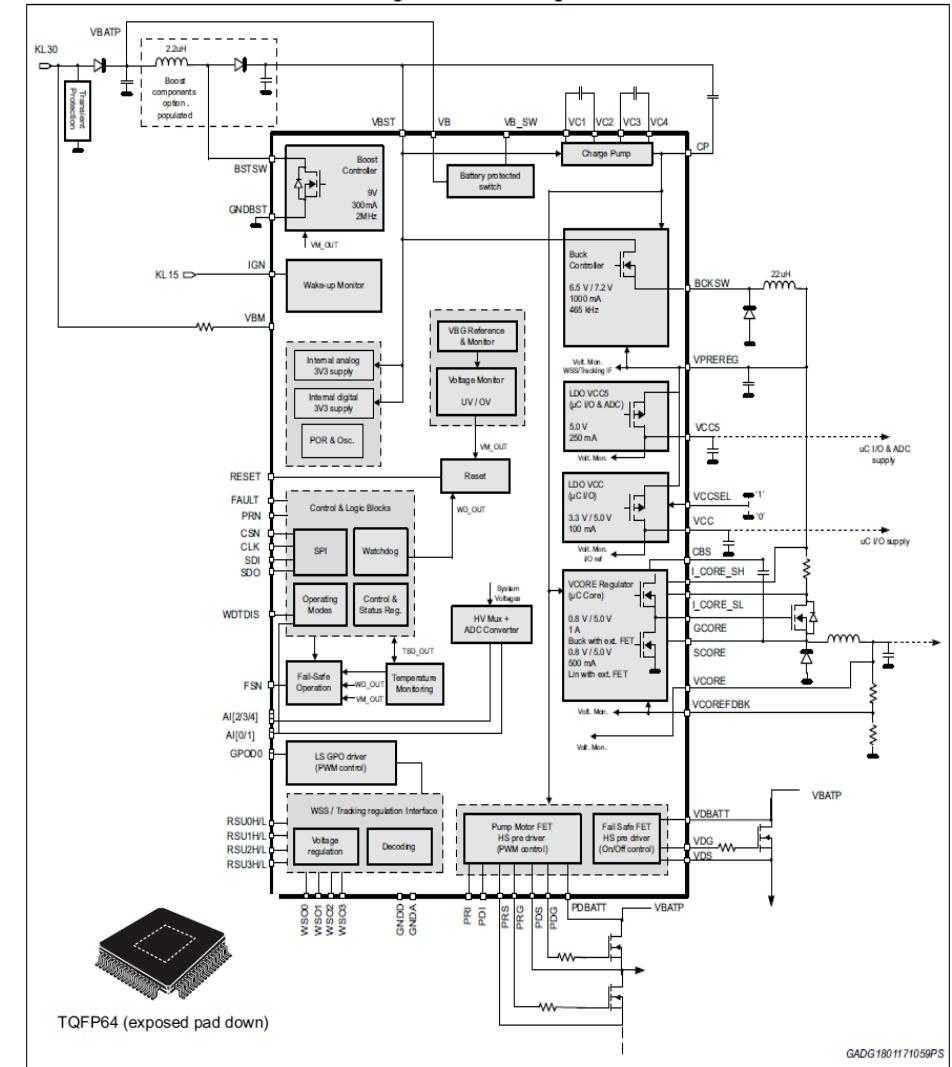
1200V discrete

Part Number	V _{DS} [V]	R _{DS(on)} Typ @ 25°C [Ω], *V _{GS} =18V	Package	Eng. Samples	Mat.30
SCT070HU120G3AG	1200	0.070	HU3PAK	Available	Q1 2022 
SCT070H120G3AG			H2PAK-7L	Available	Q1 2022 
SCT070W120G3AG			HiP247	Available	Q1 2022 
SCT070W120G3-4AG			HiP247 4L (LL)	Available	Q2 2022 
SCT040HU120G3AG	1200	0.040	HU3PAK	Q1 2022	Q2 2022 
SCT040H120G3AG			H2PAK-7L	Q1 2022	Q2 2022 
SCT040W120G3AG			HiP247	Q1 2022	Q2 2022 
SCT040W120G3-4AG			HiP247 4L (LL)	Q1 2022	Q2 2022 
SCT025HU120G3AG	1200	0.027	HU3PAK	Q1 2022	Q2 2022 
SCT025H120G3AG			H2PAK-7L	Q1 2022	Q2 2022 
SCT025W120G3AG			HiP247	Q1 2022	Q2 2022 
SCT025W120G3-4AG			HiP247 4L (LL)	Q1 2022	Q2 2022 
SCT020HU120G3AG	1200	0.020	HU3PAK	Available	Q2 2022 
SCT020H120G3AG			H2PAK-7L	Available	Q2 2022 
SCT016H120G3AG	1200	0.016	H2PAK-7L	Q1 2022	Q1 2022 
SCT016HU120G3AG			HU3PAK	Q1 2022	Q2 2022 
SCT015W120G3-4AG	1200	0.015	HiP247-4L	Available	Q2 2022 

L9396 System Basis Chip

Technical information

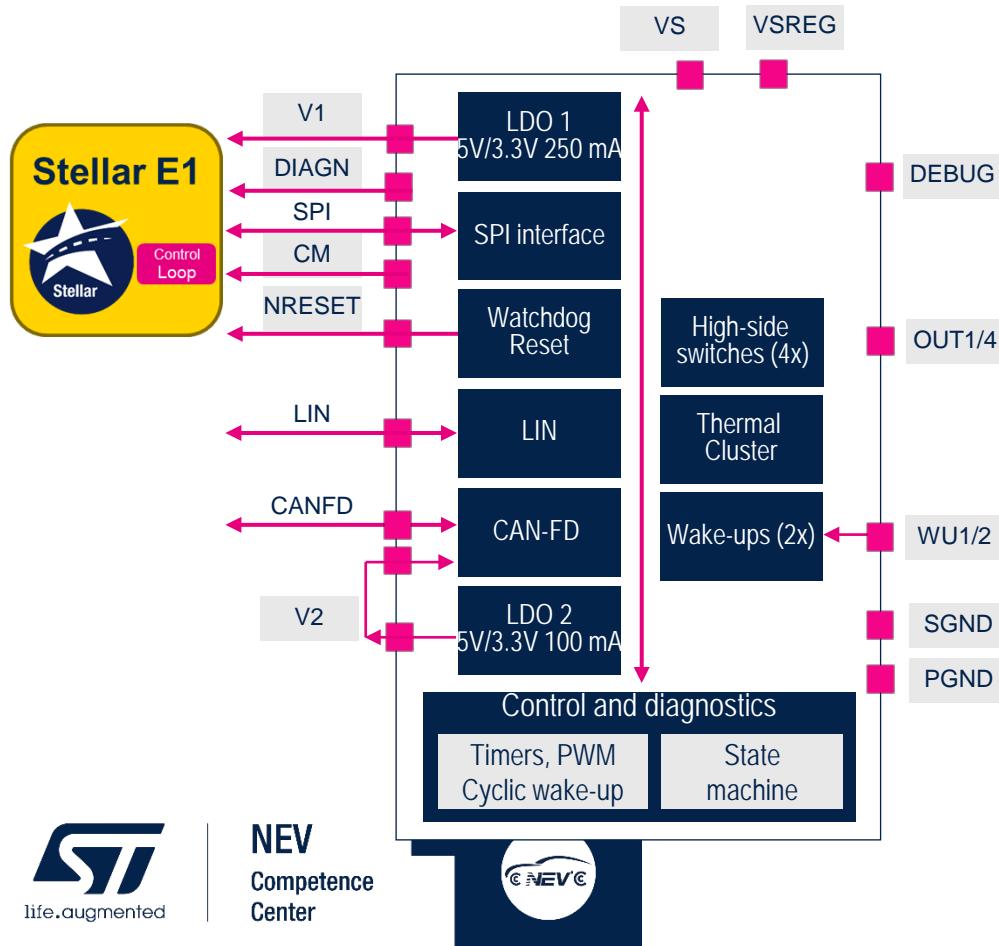
- Integrated boost regulator, 9 V, 300 mA, 2 MHz
- Integrated buck pre-regulator, 6.5 V / 7.2 V, 1 A, 465 kHz
- Integrated LDO, 5 V, 250 mA for µC I/O and ADC supply
- Integrated configurable LDO, 3.3 V / 5 V, 100 mA for µC I/O supply
- Configurable and programmable regulator with external FET, 0.8 V to 5 V for µC core supply
 - up to 1 A in buck configuration
 - up to 750 mA in linear configuration
- 2x tracking regulator supply (3.3 V / 5 V, 120mA)
- Configurable and programmable double watchdog (Q&A WD and PRUN WD)
- Fail-Safe Output (FSN) and Configurable Fail-Safe Functionality
- Wake-up input (IGN) (standby current consumption: 30µA)
- Low-side general purpose output with programmable PWM control (GPO)
- Integrated 10-bit ADC with system diagnostics
- Operating voltage: VBATP: 4.5 V to 19 V with boost; 6 V to 19 V without boost
- ISO 26262 compliant, ready for functional safety application up to ASIL-D



Power management for Stellar E1

Highly integrated and scalable SBC & PMIC for advanced MCUs

**SPSB081: SBC with dual configurable LDO, LIN and CAN-FD.
Team mating with Stellar E1 to support Electrification**



- LDO1 5V/3.3V@250 mA, LDO2 5V/3.3V@100 mA
- Watchdog
- 2xWake up inputs
- Overvoltage detection
- All Outputs Short Circuit protected
- Dedicated diagnostic pin
- Temperature Warning and Thermal Shutdown
- CAN-FD
- LIN (optional)
- SPI for Mode Control and Diagnosis
- Very low Stand-By Current
- Thermal Clusters
- Direct Input
- ASIL-B



Fulfilling Stellar family with scalable solutions

SPSA068

- PMIC with 1 Buck (5V, 3V3) @ 1A load current + 1 Vref @ 20mA
- Battery compatible
- Low power mode (<75uA active not switching)
- Internal compensation
- Window WD and Reset
- Voltage and current supervisors, Fault pin
- OTP parameters and SPI
- ASIL-B



L99VR02J

- Configurable LDO, 500mA max out
- Advanced diagnostics, battery compatible
- ASIL-B



**SPSB110
SPSB083**

Under definition



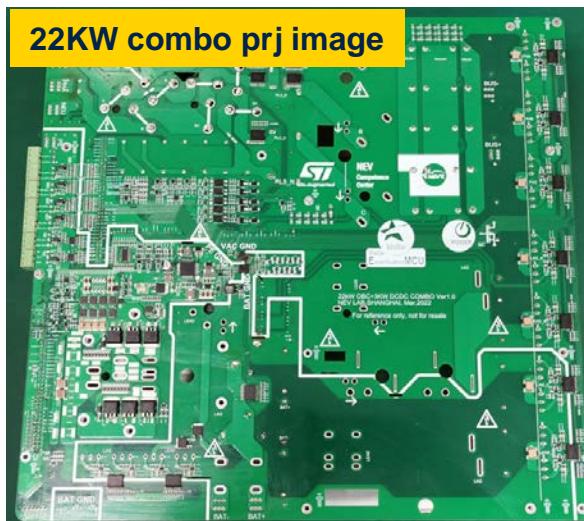
22kw obc+3kw dc/dc combo system solution introduce

Sep,2022

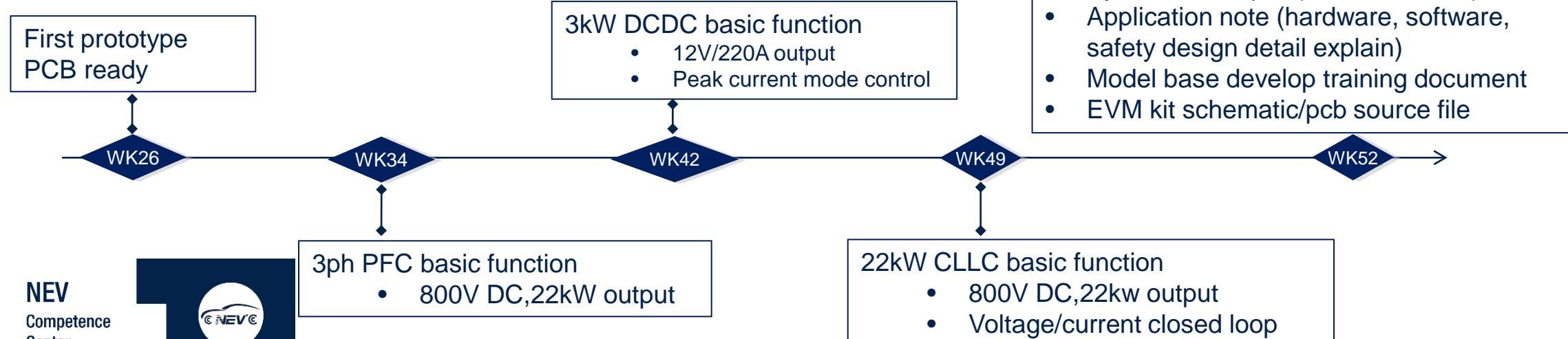
NEV
Competence
Center



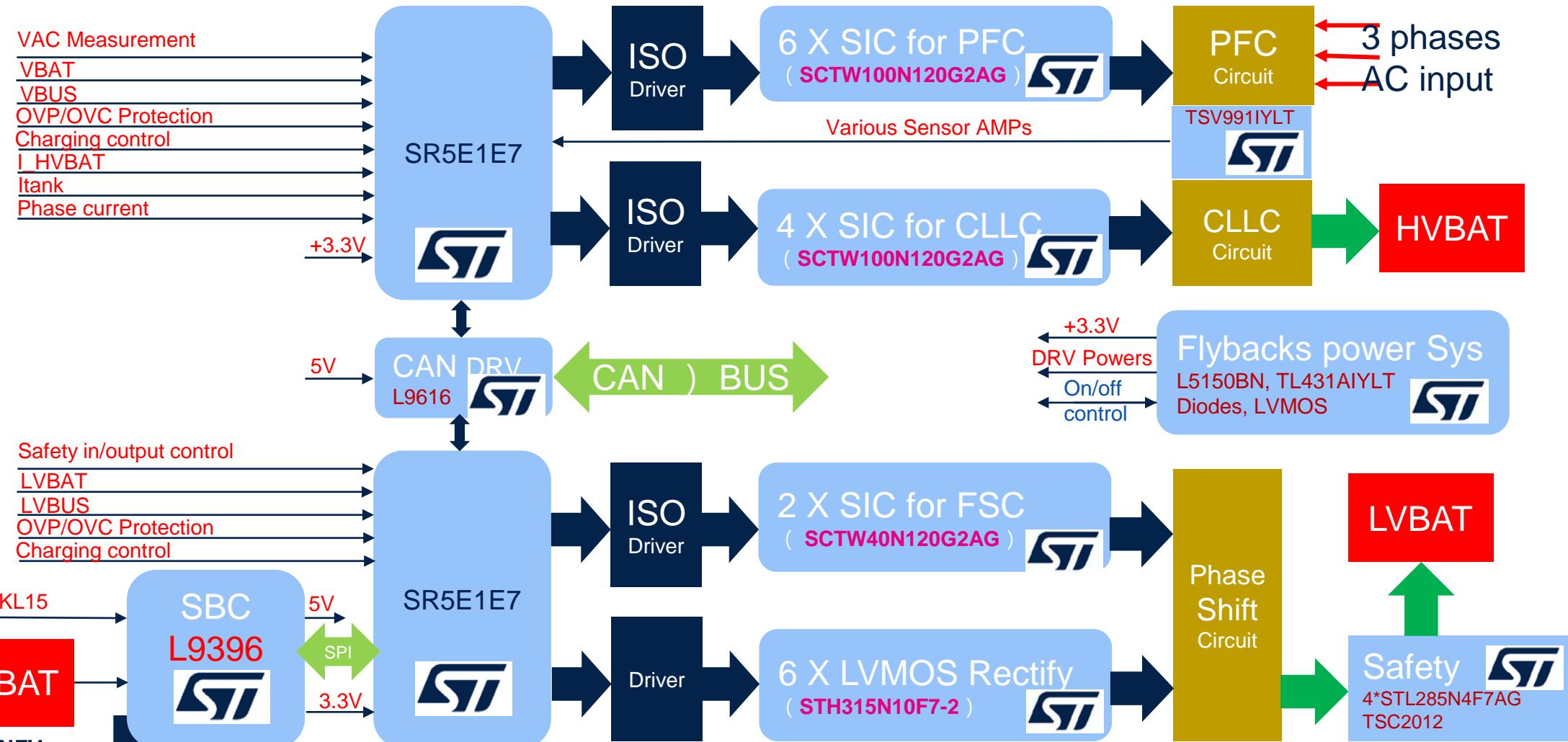
22kW OBC+DCDC Combo prj summary & schedule



Combo project main schedule(Y2022)

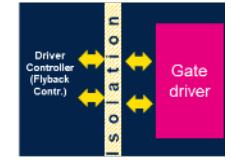


22kw OBC+DCDC combo solution structure -Stellar-E MCU+1200V SiC MOSFET



22kW OBC combo solution highlight benefits

developing



Name	Part number
Microcontroller	<ul style="list-style-type: none">SR5E1E7
1200V SiC (Gen3 pending)	<ul style="list-style-type: none">SCTW100N120NG2AGSCTW40N120G2VAG
LV MOSFET	<ul style="list-style-type: none">STH315N10F7
SBC	<ul style="list-style-type: none">L9396STPM066TSV791IYLT
Analog	<ul style="list-style-type: none">TSV911IYLTTSC2011IYDT

Technical highlights

- Stellar-E MCU digital control to best leverage SiC/GaN
- Full SiC MOSFET with 800V and efficiency optimized
- Synchronization rectification solution for CLLC
- Peak current mode control solution for AUX DCDC(PSFB)
- One MCU platform to handle power loop and vehicle control (OTA, ASIL-D, CAN-FD, AUTOSAR)

22kw OBC+3kw DCDC power stage spec

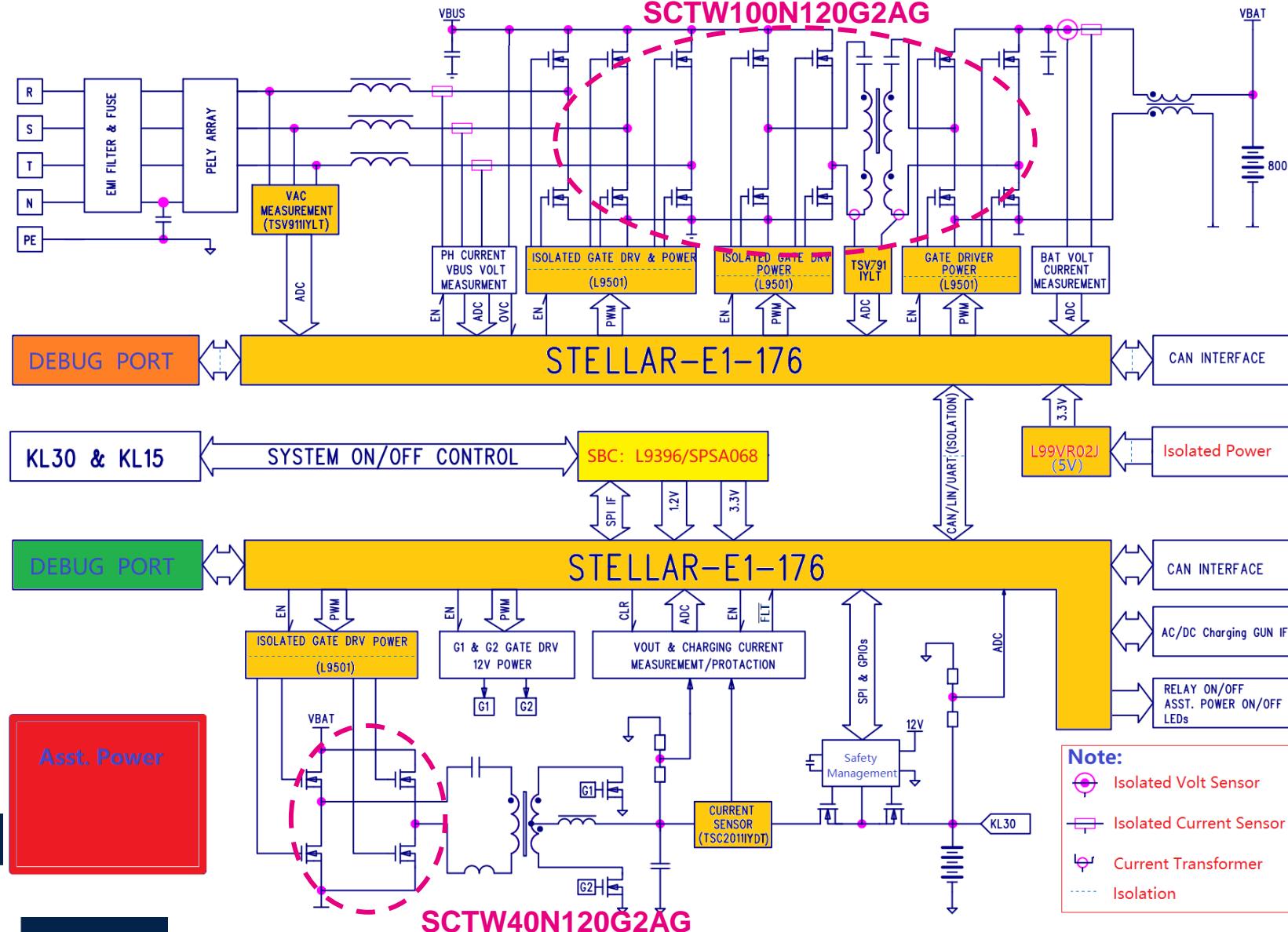
- 3ph 22KW OBC spec

Parameter	3phase AC input charging
Input Voltage	304Vac~456Vac, @380V,50Hz
Output voltage	450-900V DC →450-900V @800V battery
Output power	→22kW 36A max @800V
DC bus voltage	650-900V DC
Switching frequency, PFC/CLLC	50kHz/200kHz
Communication	CAN/CAN-FD
Housing	Water cooling

- 3KW DCDC spec

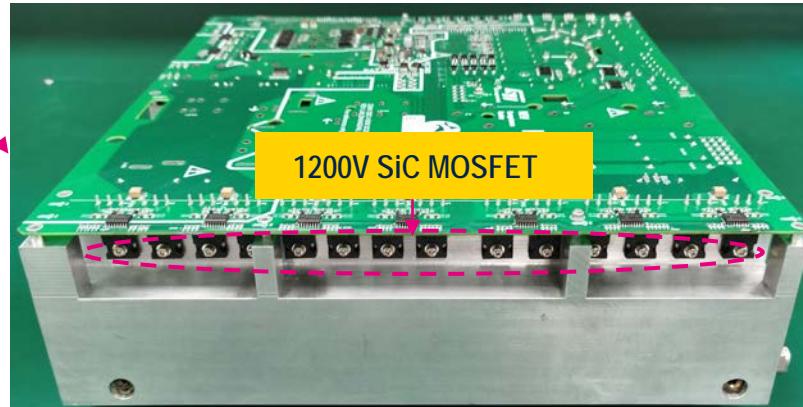
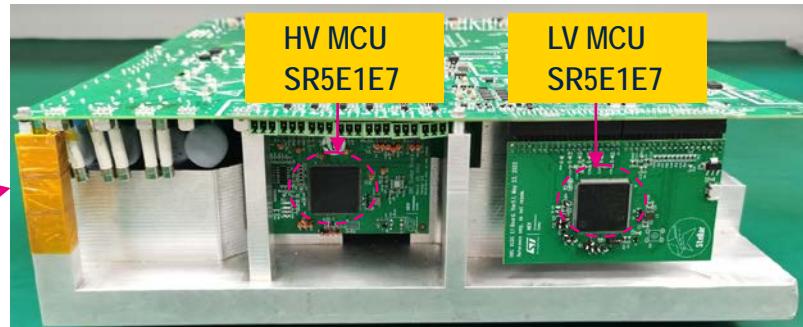
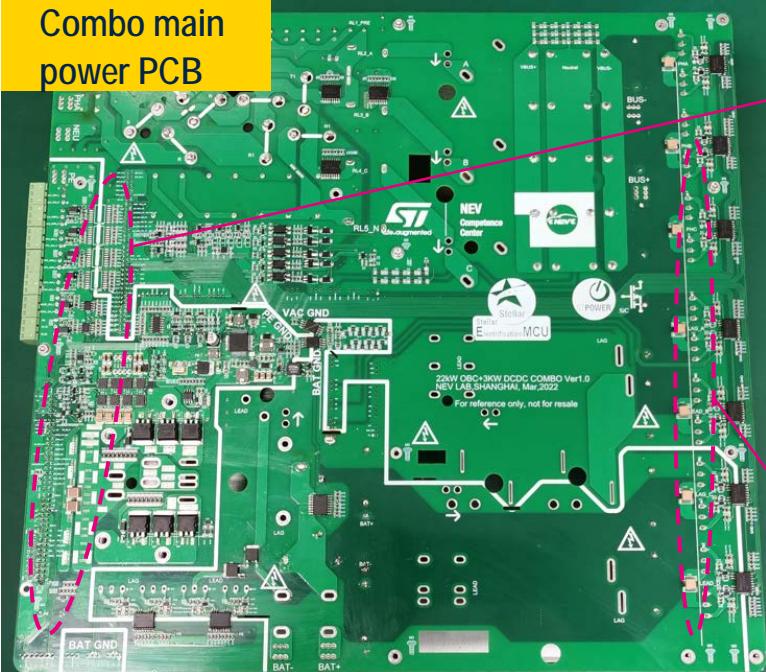
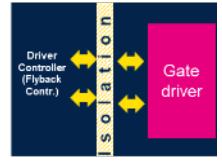
Parameter	Value
Input Voltage	450-900V DC@800V
Output voltage	9-16V @14V
Output power	3kW
Power stage frequency	100kHz
Output ripple	<280mV@full power
Communication	CAN/CAN-FD
Housing	Water cooling

22kw OBC+DCDC combo power topology -Stellar-E MCU+1200V SiC MOSFET



ST highlight component in 22kW combo platform

developing

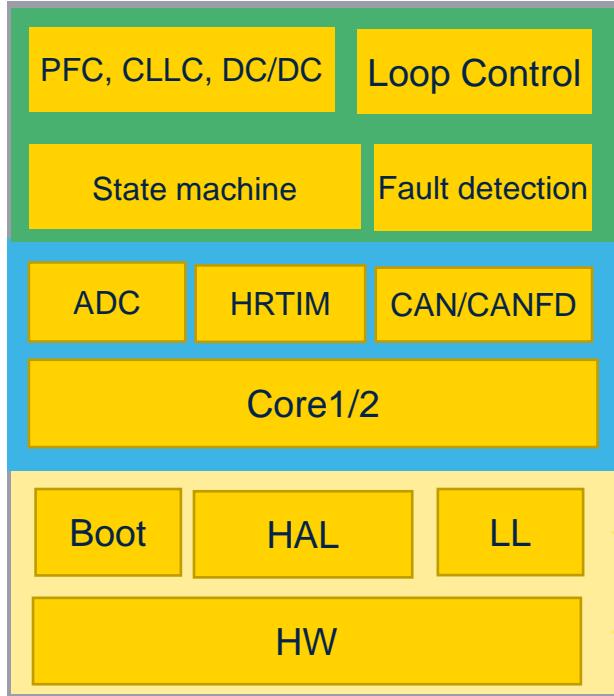


Name	Part number
Microcontroller	<ul style="list-style-type: none">SR5E1E7SCTW100N120NG2AG
1200V SiC (GEN3 pending for test)	<ul style="list-style-type: none">SCTW40N120G2VAGSTH315N10F7
LV MOSFET	<ul style="list-style-type: none">L9396STPM066
SBC	<ul style="list-style-type: none">TSV791IYLTTSV911IYLT
Analog	<ul style="list-style-type: none">TSC201IYDT





22kW Combo system SW structure



- Model-Based Design
- V model process
- PFC, CLLC, DC/DC Applications
- Multicore
- Docs & Quality



NEV
Competence
Center



Application

- MIL Test
- Loop control design
- State machine

Peripheral drive

- ADC sampling
- HRTIM PWM
- CANFD communication

Stellar Studio / SDK

- Code integration and compilation



debugger



CAN/CANFD

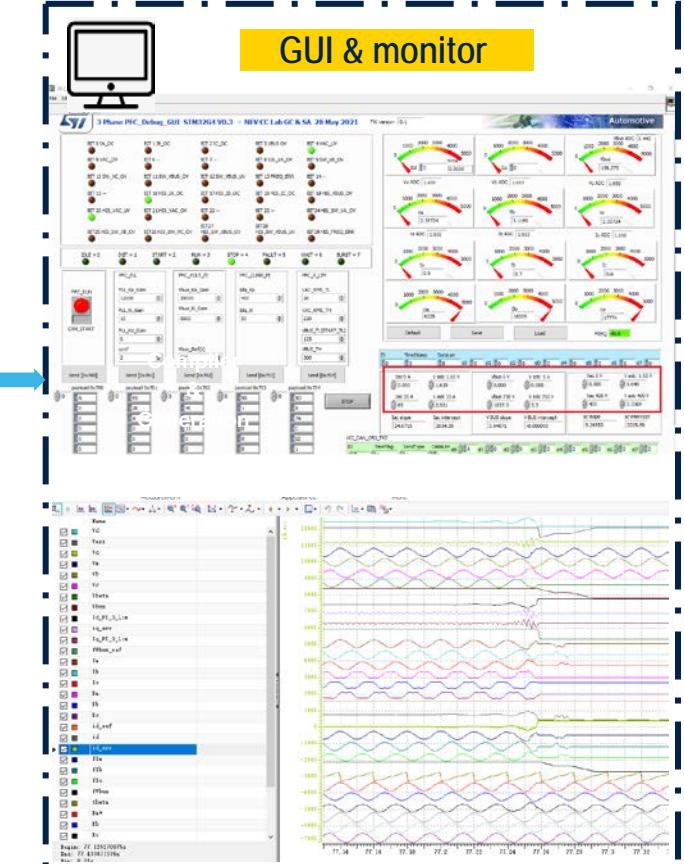
Program
Download



GUI

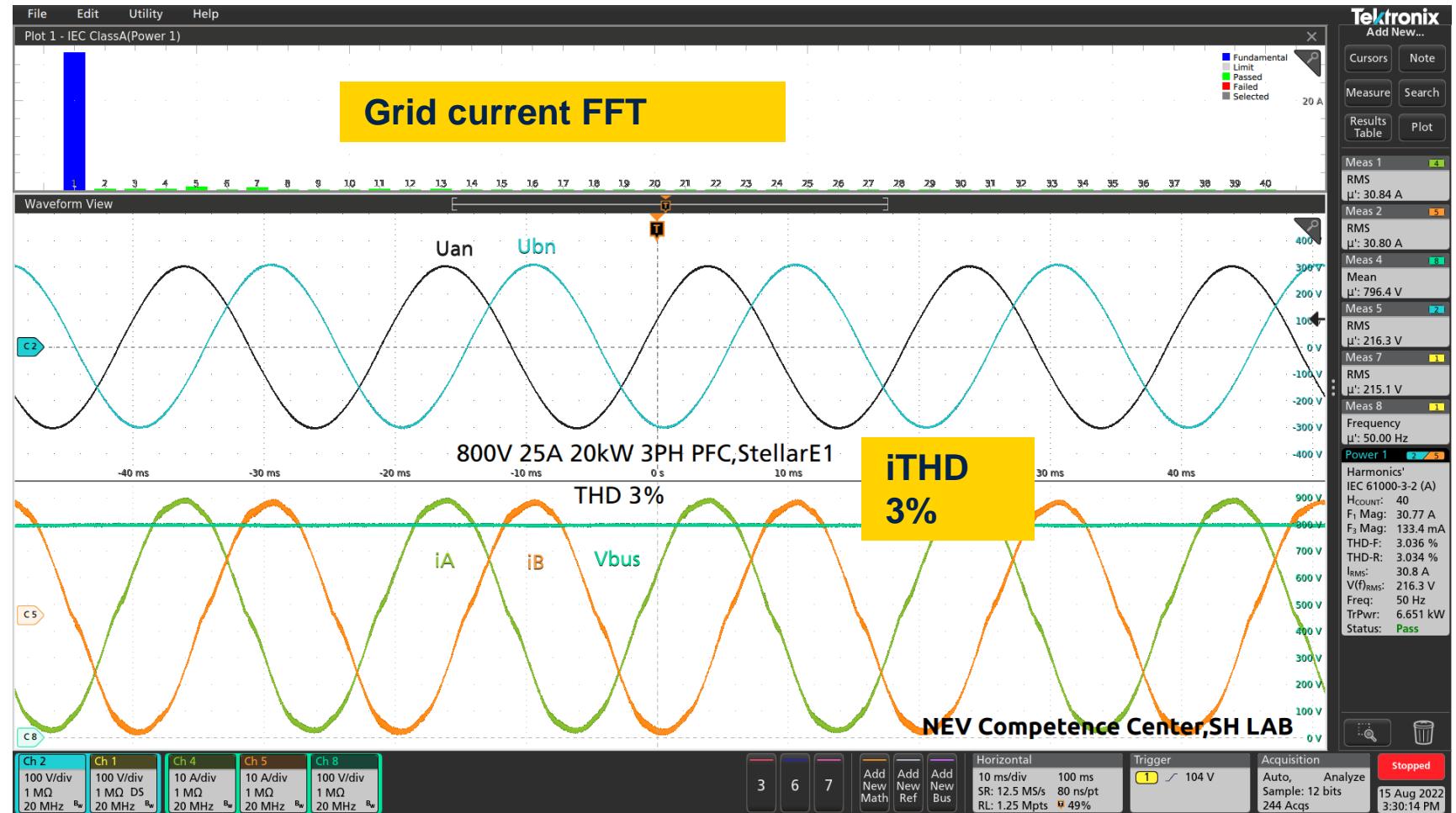
- Status monitor
- System configuration

GUI & monitor



3ph PFC full power running

- Input:380VAC(L-L),32A RMS
- Output:800VDC,25A,20KW
- **iTHd:3%**
- Control loop : every cycle(50kHz)
- SiC water cooling, PFC inductor force air, ambient temp 25°C · water temp 21°C

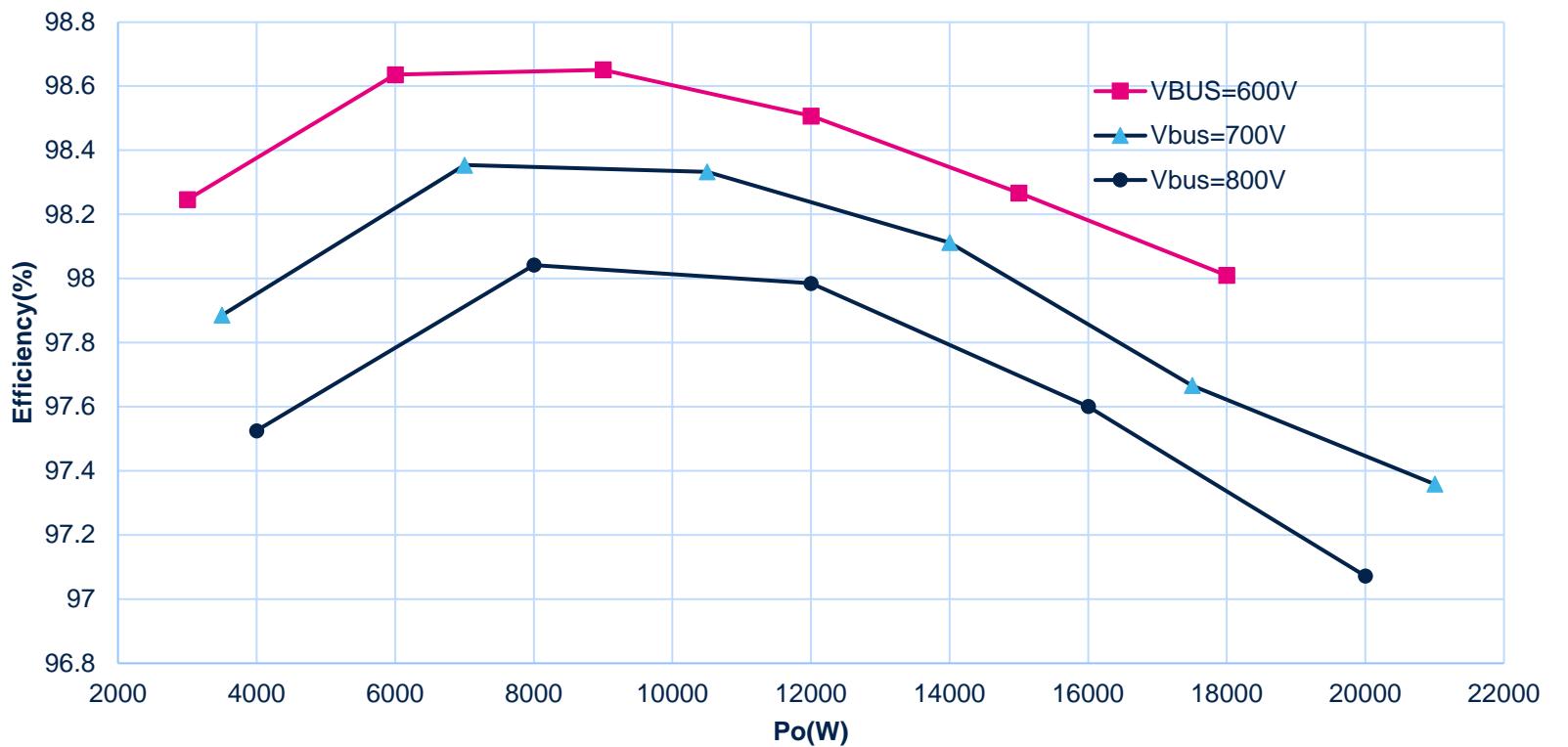


3ph PFC efficiency

- Peak efficiency **98.63%**
- 800V/20KW full load efficiency **97.07%**

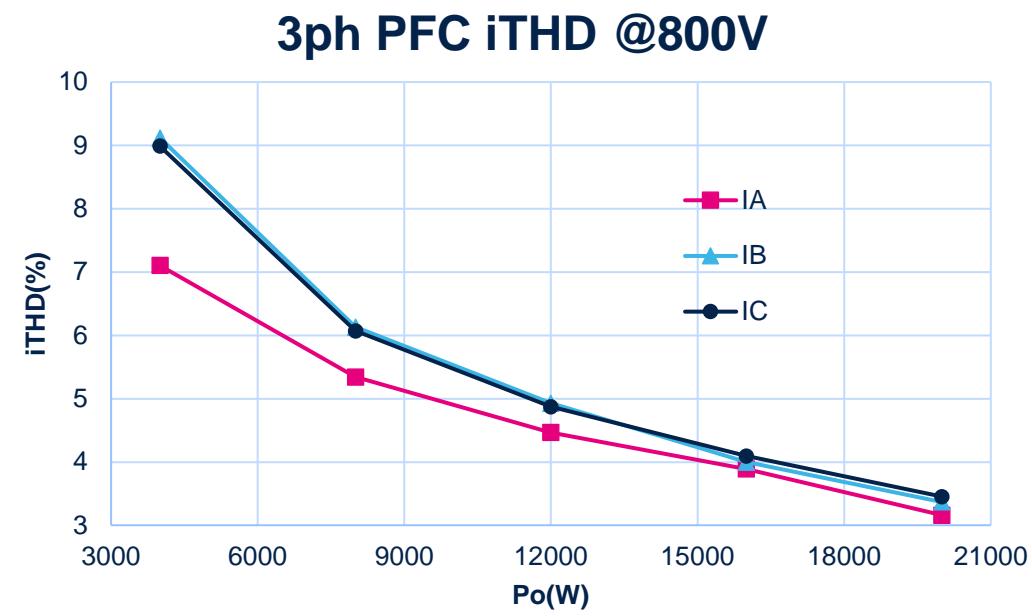
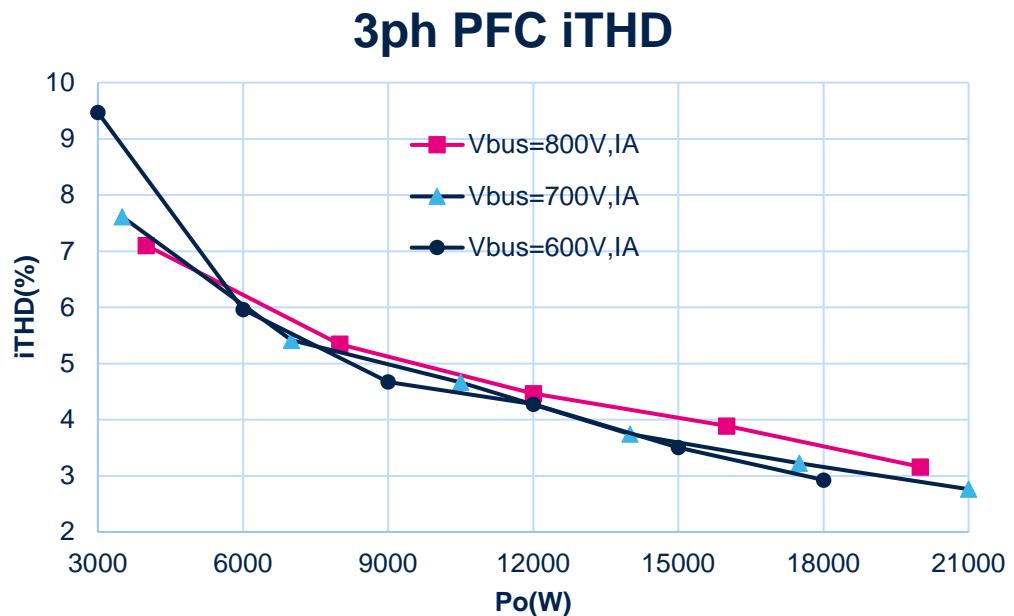
- Peak efficiency:98.63%
- Input:380VAC(L-L)
- Switching frequency:50kHz
- Topology:2 level PWM rectifier(B6)
- Dead-time:300ns
- R_{on}=5.1R,R_{off}=6.8R
- Chroma power resistor load and WT5000 power analyzer
- Bias power not included

3ph PFC efficiency



3ph PFC iTHD(%) data

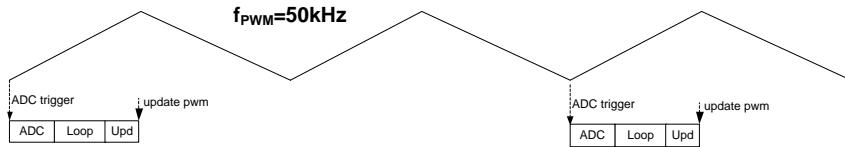
- Full load iTHD 2.76% @700V/30A (requirement <5% ?)
- Three phase iTHD good consistency



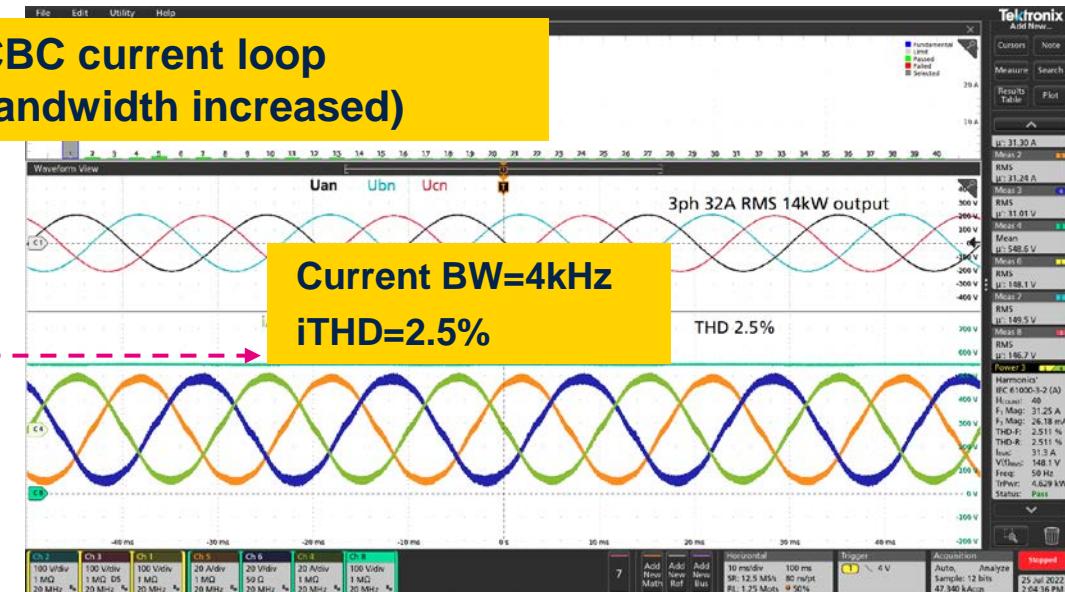
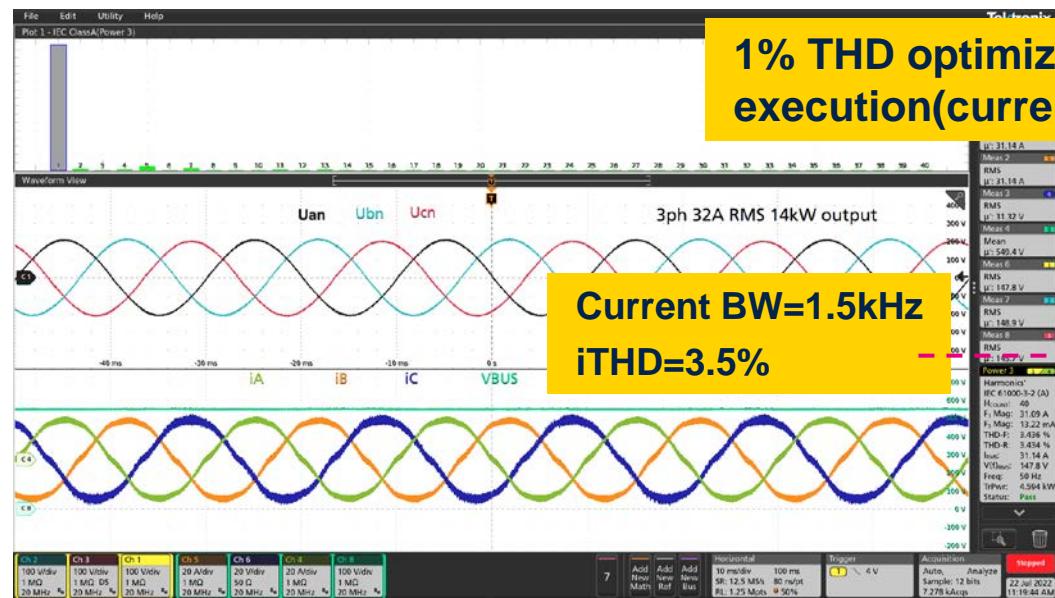
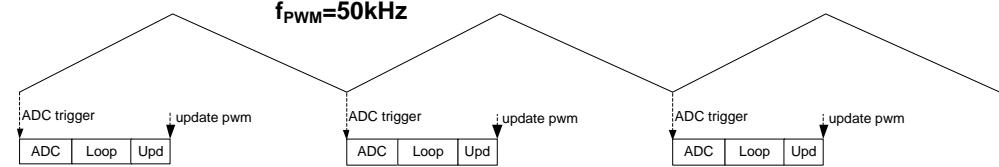
- Input:380VAC(L-L)
- Current loop execute : cycle by cycle(50kHz)
- Switching frequency:50kHz
- Dead-time:300ns
- Chroma power resistor load 63224E and power analyzer WT5000

iTHD optimized with cycle by cycle(CBC) control loop updating

Control loop updating **every two** PWM cycle



Control loop updating **every** PWM cycle

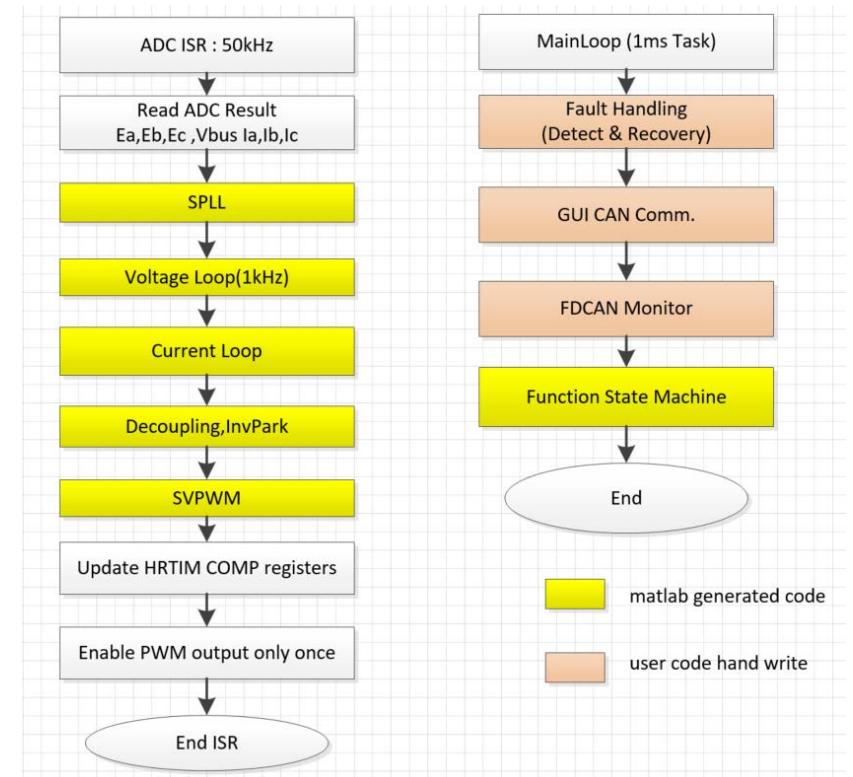


Control loop execution time with Stellar-E

- current loop execute at 50kHz(CBC) and total execution time 6.1us, very low CPU load
- yellow part is Simulink(MATLAB) generated loop control and state machine code

Task Name		Execution Frequency	Execution time	Function
	Voltage loop	1KHz	1.58us	Voltage loop control
VSR_Code_G()	PLL	50KHz	6.13us	Electric angle calculation
	Current loop	50KHz		DQ axis current loop control
	DQ axis	50KHz		DQ axis current decoupling
	Coordinate transformation and SVPWM	50KHz		Include Clark, Park, Inv-Clark, Inv-Park transformation and SVPWM function
pfc_mainState()	1KHz	690ns	System state machine	
MainLp_Cali_PFC_CAN_Task()	1KHz	2.08us	GUI calibration	
MainLp_ECU_CAN_Task()	1KHz	16us	Display system variables curve	
PFC_FaultCheck()	1KHz	1.18us	System fault check and recovery	

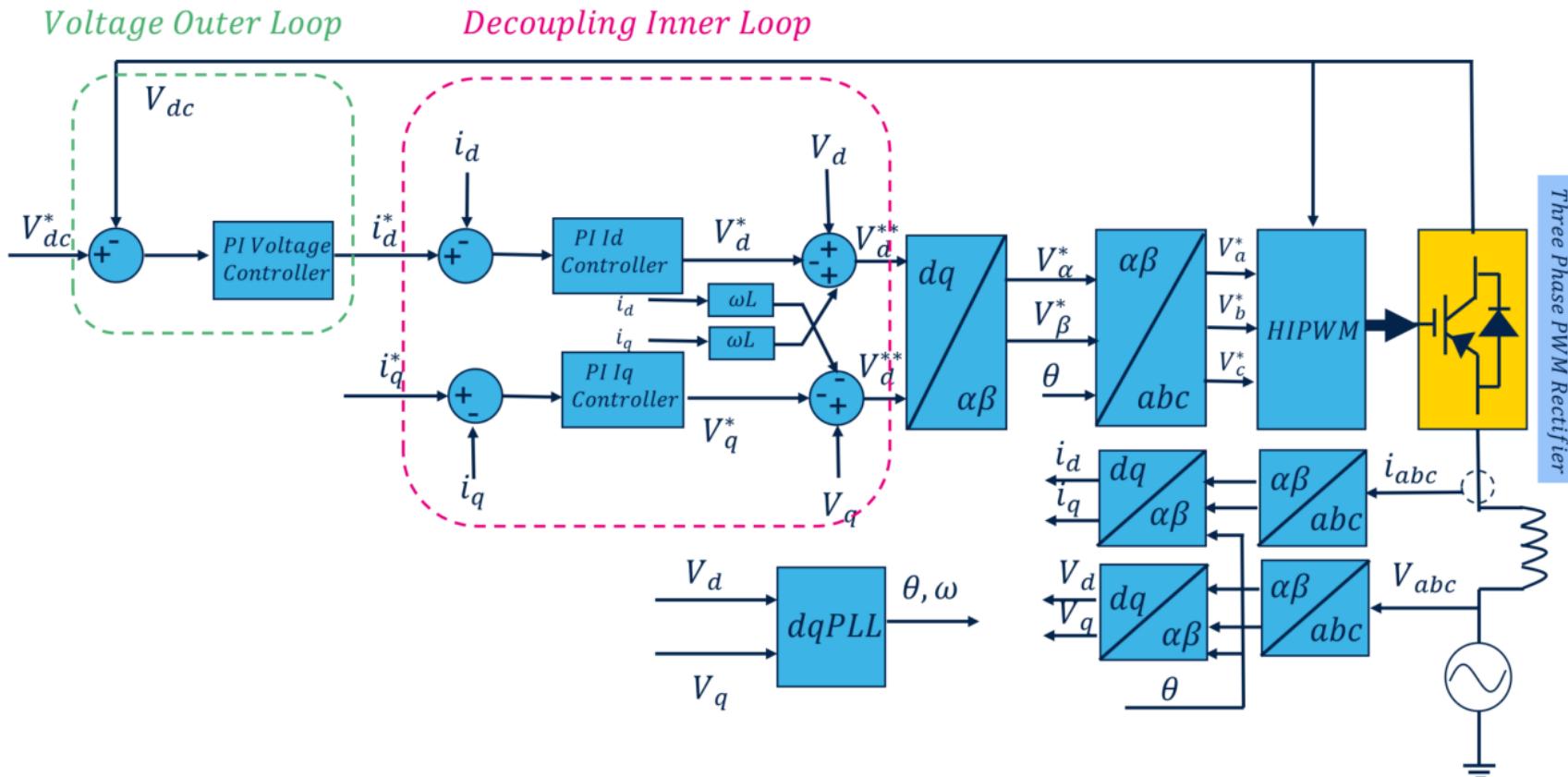
ADC ISR and main loop SW task



Voltage-oriented Vector Control Diagram Block

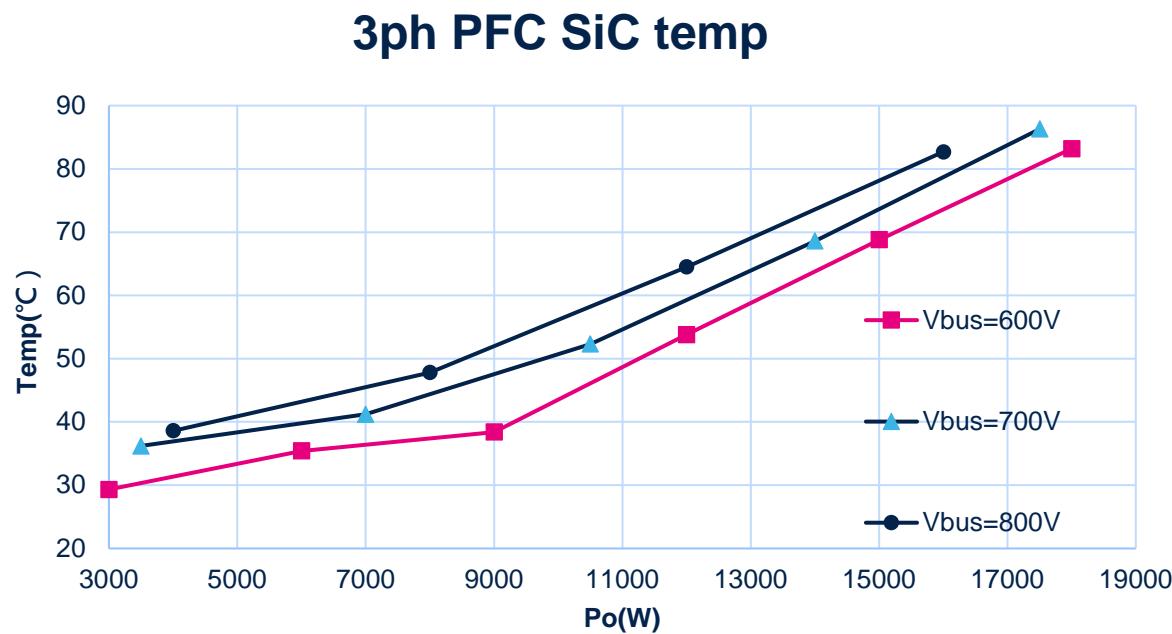
- Current decoupling inner loop and voltage outer loop control
- dqPLL electric angle and frequency calculation
- Harmonic injection pulse width modulation
- Notch filter for bus voltage sampling

PFC Voltage-oriented vector control strategy

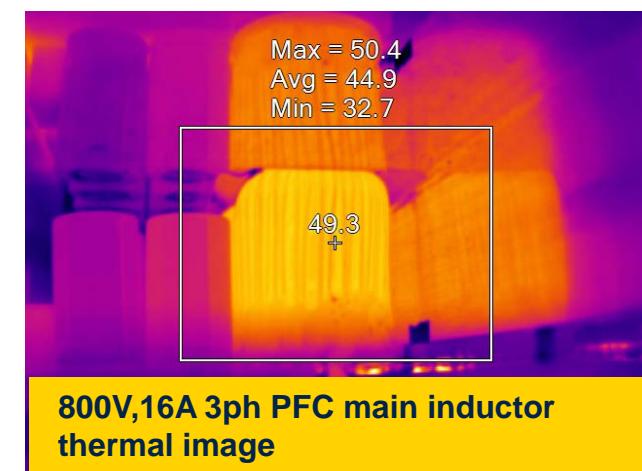
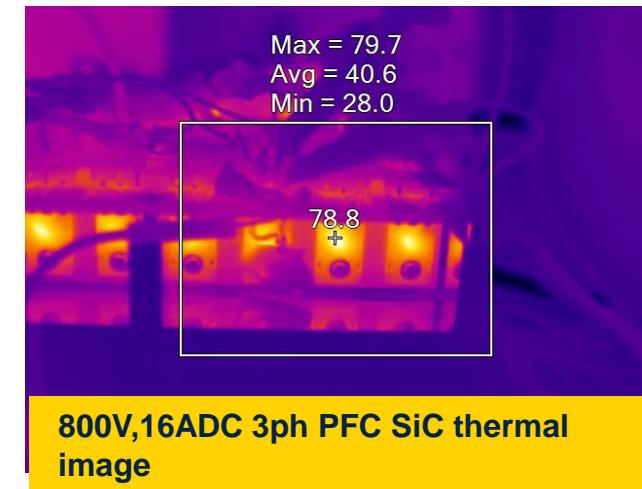


System thermal stress

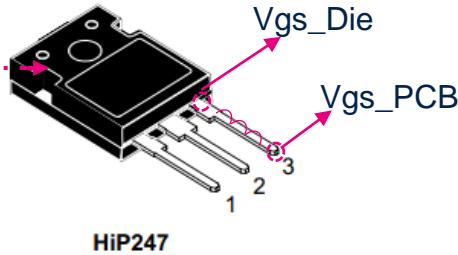
- Higher bus voltage, SiC thermal stress is worse
- 30mOhm,1200V SiC @40kHz suggested for 22kW 3ph PFC



- SiC water cooling, PFC inductor force air, ambient temp 25°C · water temp 21°C
- Input:380VAC(L-L)
- Switching frequency:50kHz
- Dead-time:300ns
- R_{on}=5.1R, R_{off}=6.8R



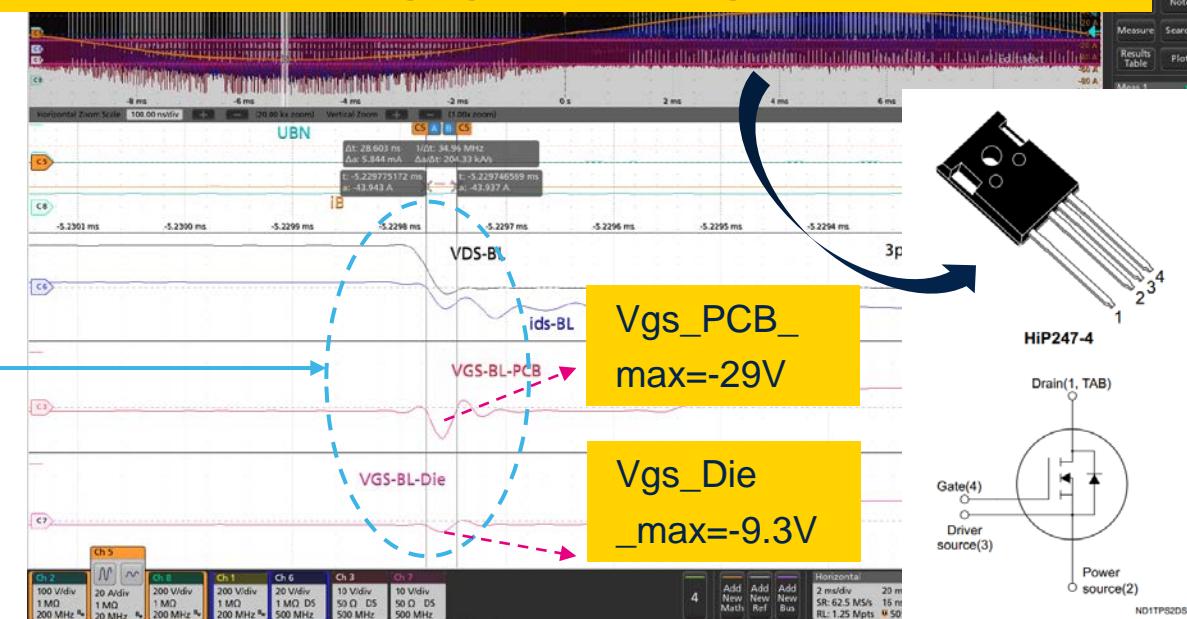
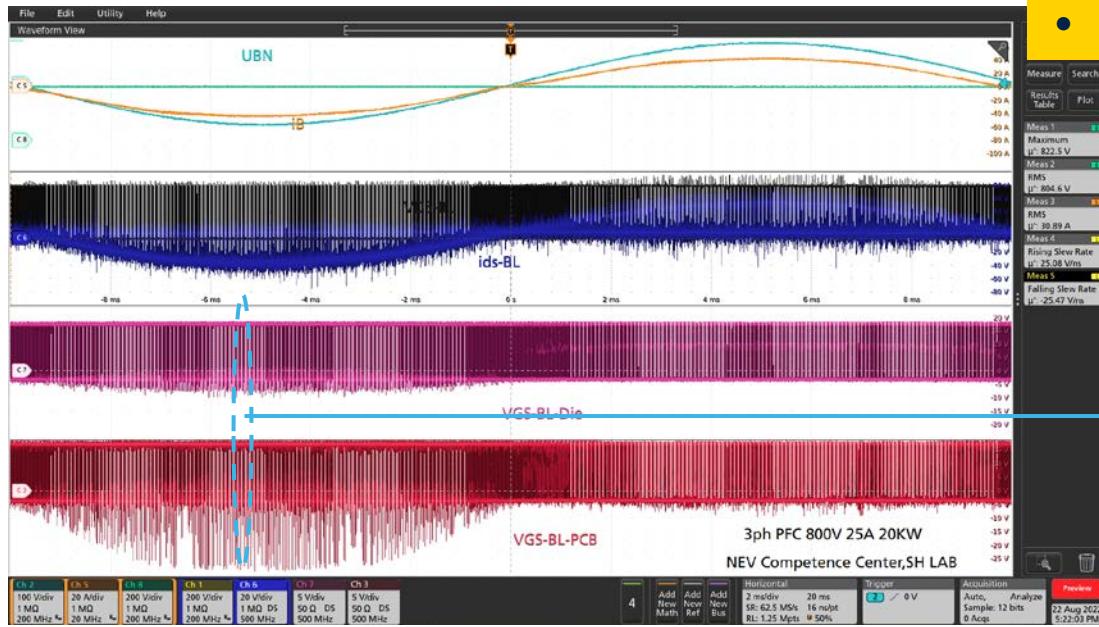
#1 3ph PFC SiC driver-source inductor effect



SiC test probe position	Vgs glitch voltage maximum	Vgs glitch voltage duration
Vgs_die	-9.3V	28.6ns
Vgs_PCB	-28.7V	28.6ns

- Input: 380VAC(L-L), 32A RMS
- Output: 800VDC, 25A, 20kW
- $R_{on}=5.1\Omega$, $R_{off}=6.8\Omega$
- $V_{on}=17.8V$, $V_{off}=-3.6V$
- Grid current negative cycle, Vgs glitch cause by opposite SiC turn off

- Source parasitic inductor involve Vgs glitch with high di/dt
- Miller capacitor involve Vgs glitch with high dv/dt



Thank you

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